

Characterising TelePix2

Characterising a Novel Timing and Triggering Plane for use with the EUDET Telescopes at the DESY II Test Beam Facility

Arianna Wintle on behalf of the TelePix2 Team, HighRR Seminar

15/11/2023

EXZELLENZCLUSTER
QUANTUM UNIVERSE

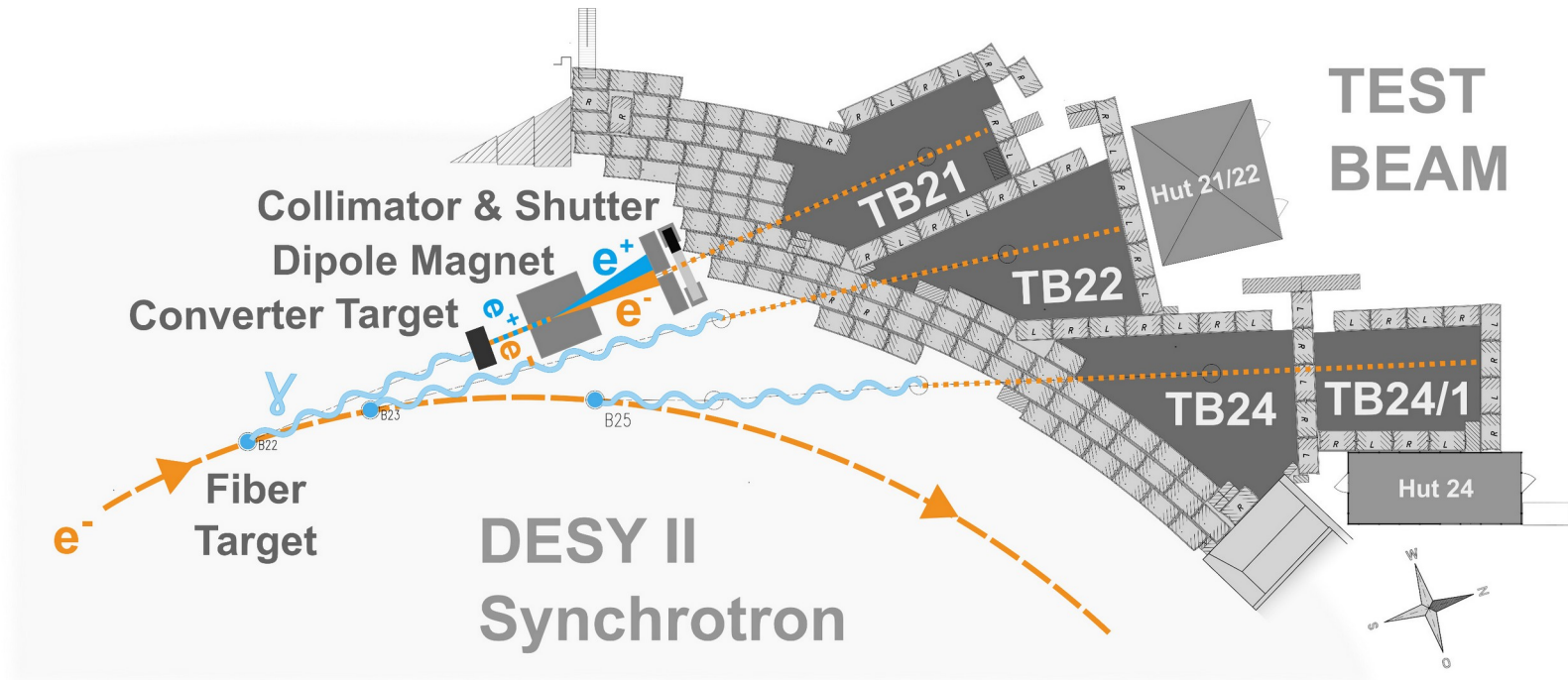
HELMHOLTZ



UNIVERSITÄT
HEIDELBERG
ZUKUNFT
SEIT 1386



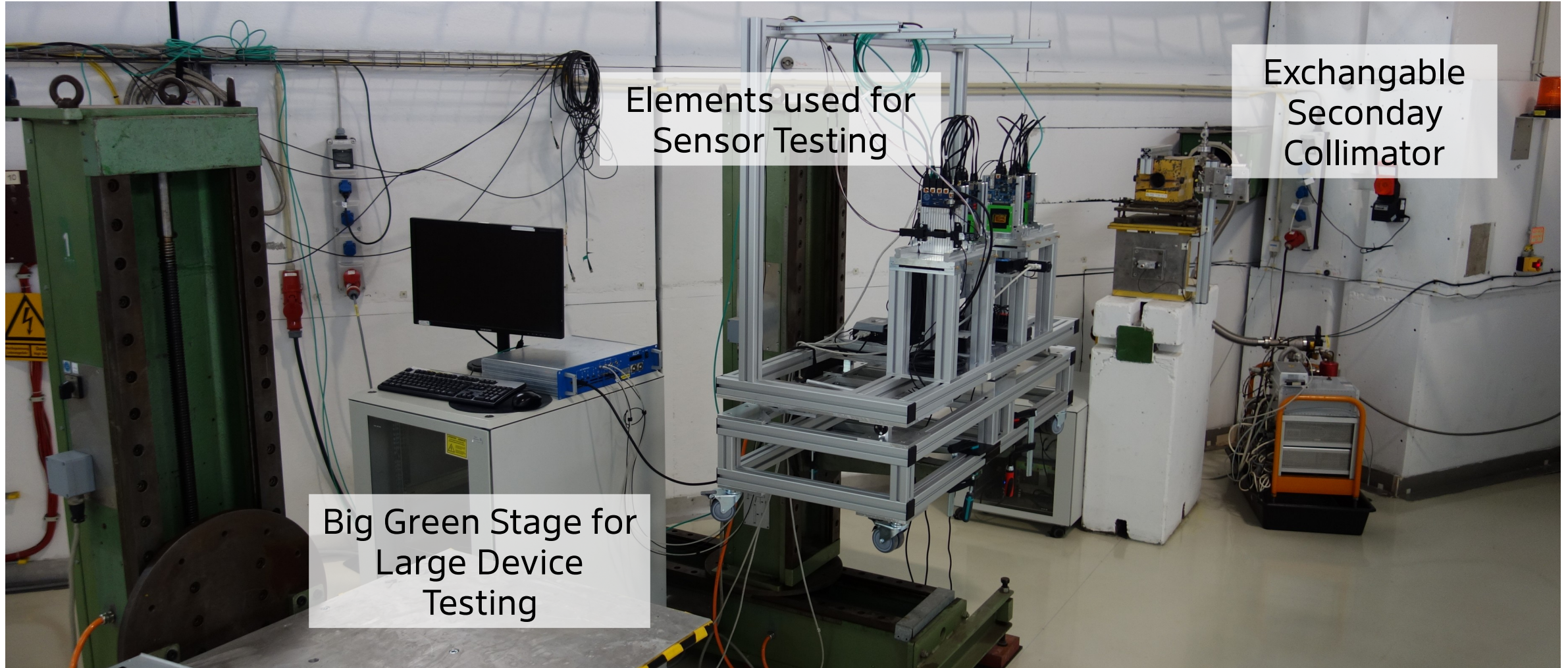
The DESY II Test Beam Facility



Three independent beamlines at the DESY II synchrotron

- Typically used for **detector R&D for characterisation**
- Offers e^- or e^+ beam with user selectable momentum from **1-6 GeV/c**
- **Shutter and primary collimator** remote controllable
- Exchangeable fixed size **secondary collimator**

Inside the Test Beam Area

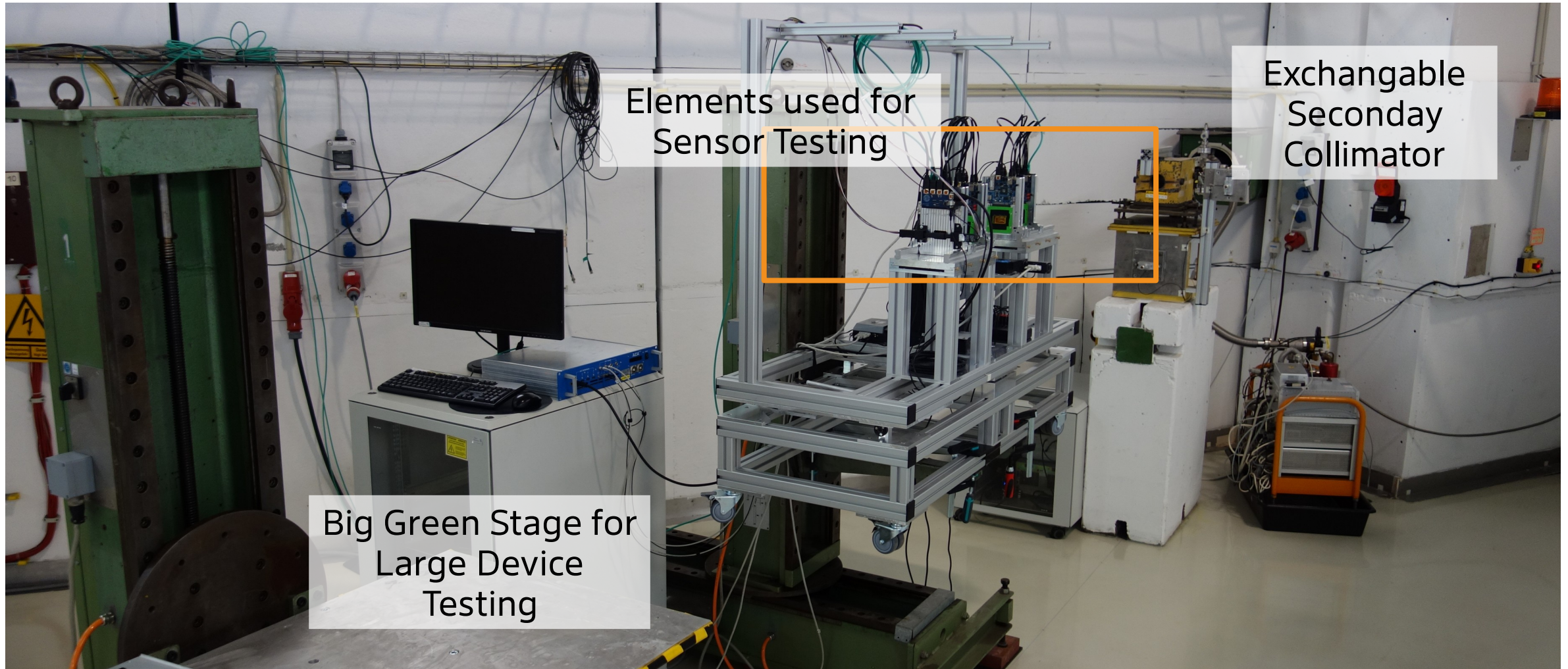


Elements used for
Sensor Testing

Exchangable
Secondary
Collimator

Big Green Stage for
Large Device
Testing

Inside the Test Beam Area



Elements used for
Sensor Testing

Exchangable
Secondary
Collimator

Big Green Stage for
Large Device
Testing

Test Beam Set Up

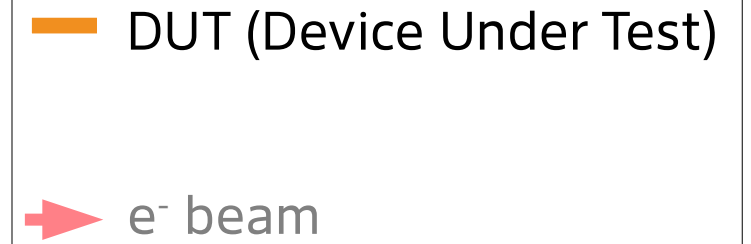
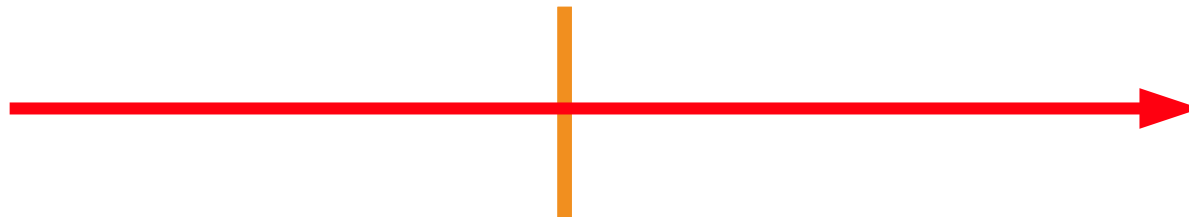
For Sensor Characterisation

DUT (Device Under Test)

Range of different sizes and operating conditions

Parameters to test:

- Efficiency
- Time Resolution & Spatial Resolution
- Behavior under a magnetic field



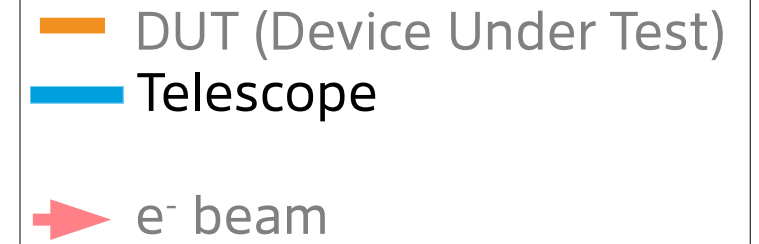
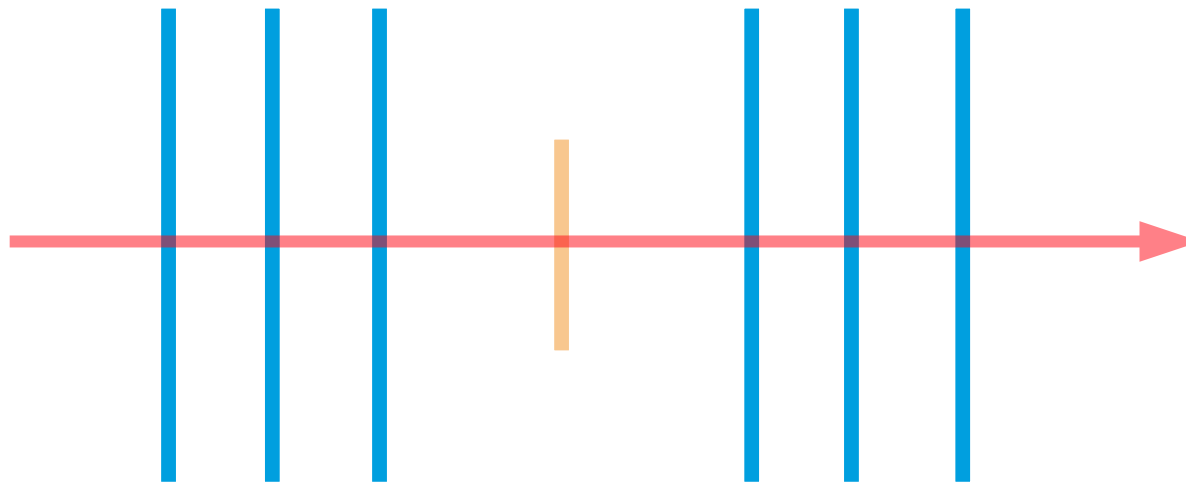
Test Beam Set Up

For Sensor Characterisation

Telescope

Multiple sensor planes
Allow precise **track** reconstruction

At DESY II Test Beam Facility two types with two different readout times:
Mimosa ($\sim 230 \mu\text{s}$) & **Adenium** ($\sim 10 \mu\text{s}$)

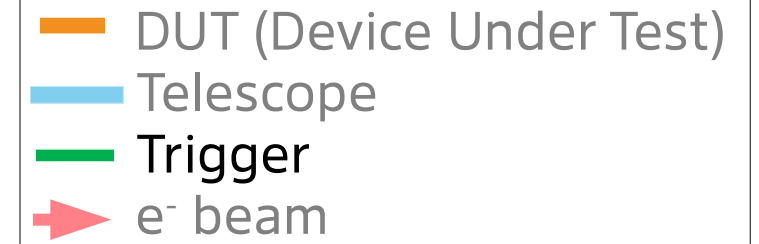
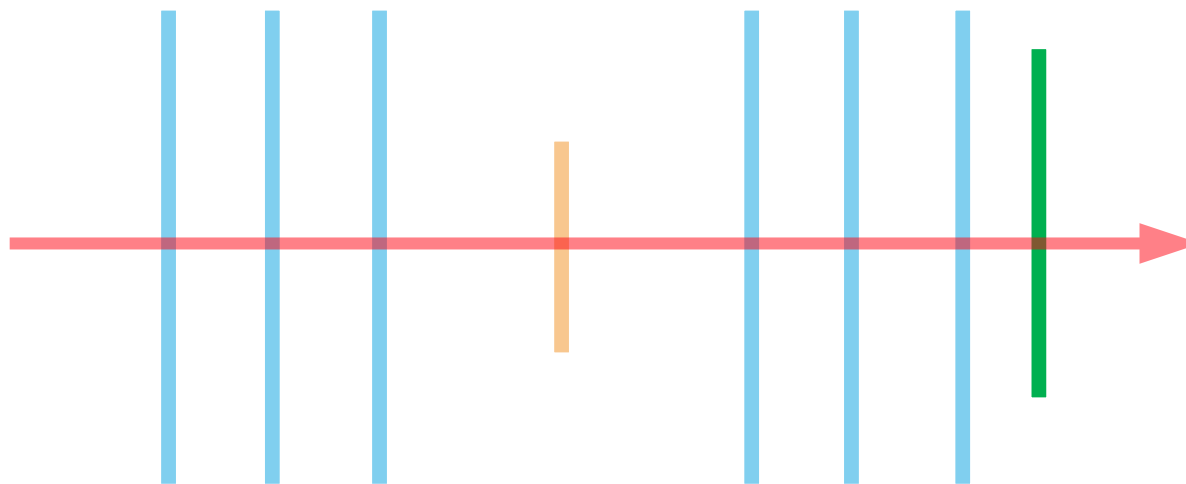


Test Beam Set Up

For Sensor Characterisation

Trigger

- Tag the presence of particles
- Important for reducing noise (event based readout)

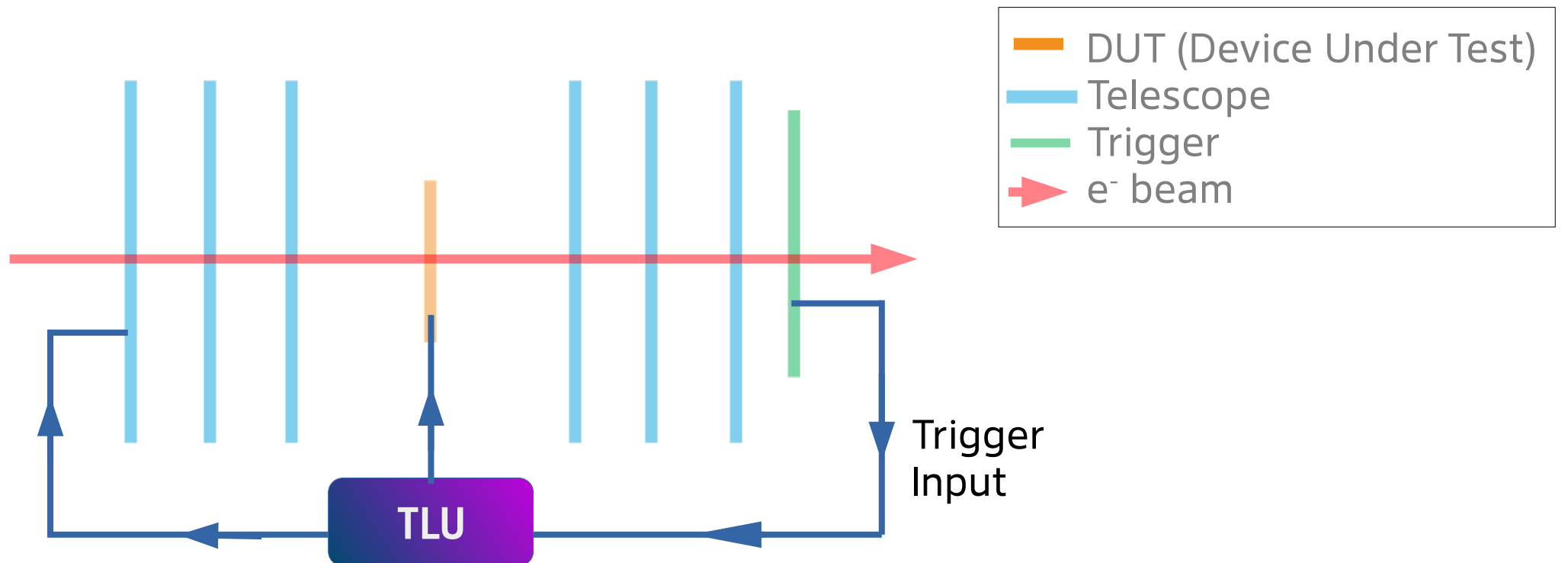


Test Beam Set Up

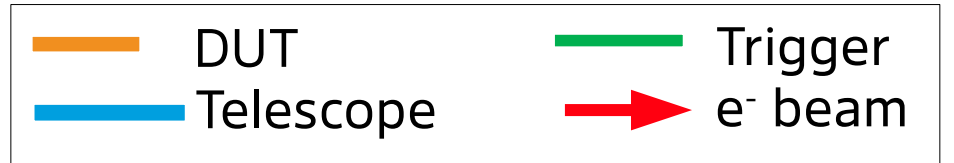
For Sensor Characterisation

Trigger Logic Unit

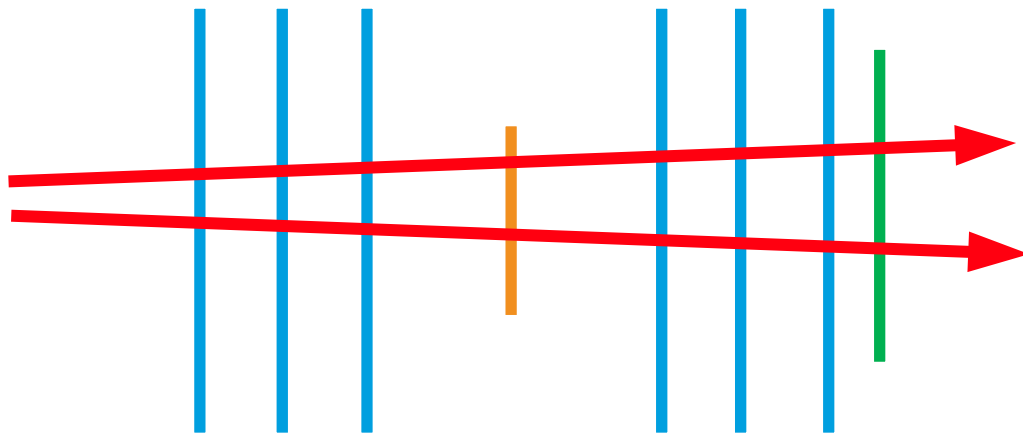
- Trigger on an arbitrary logical combination of 6 triggering inputs
- Synchronisation of multiple devices: exchange trigger ID or common clock and reset



Timing and ROI Triggering Plane

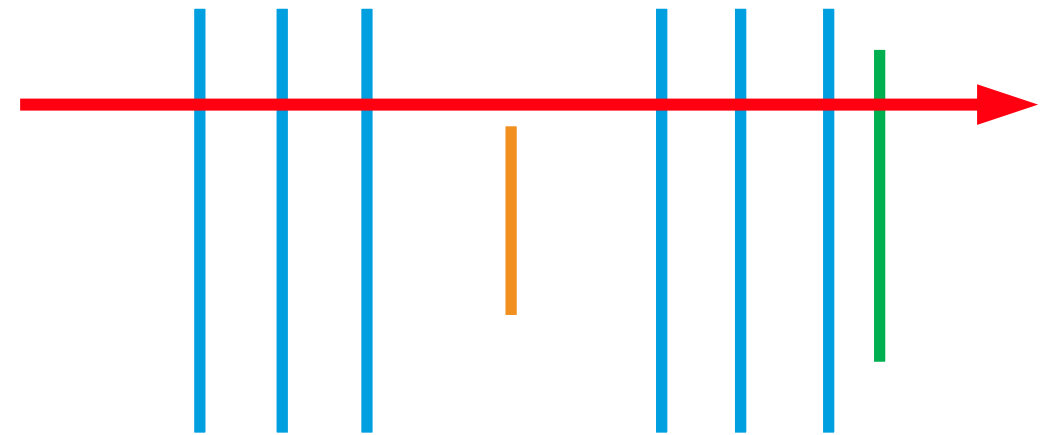


Slow telescope readout & high particle rates



Multiple tracks within one readout
→ Impossible to associate which track belongs to which trigger

Mismatch in trigger and DUT size



Trigger on uninteresting events
→ Inefficient data taking

Timing and ROI Triggering Plane

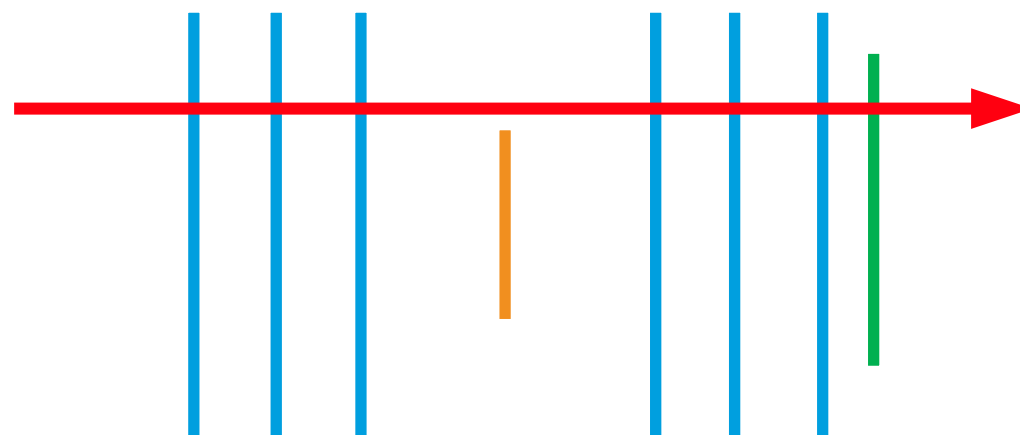


Slow telescope readout & high particle rates



Multiple tracks within one readout
→ Impossible to associate which track belongs to which trigger

Mismatch in trigger and DUT size



Trigger on uninteresting events
→ Inefficient data taking

Timing and ROI Triggering Plane

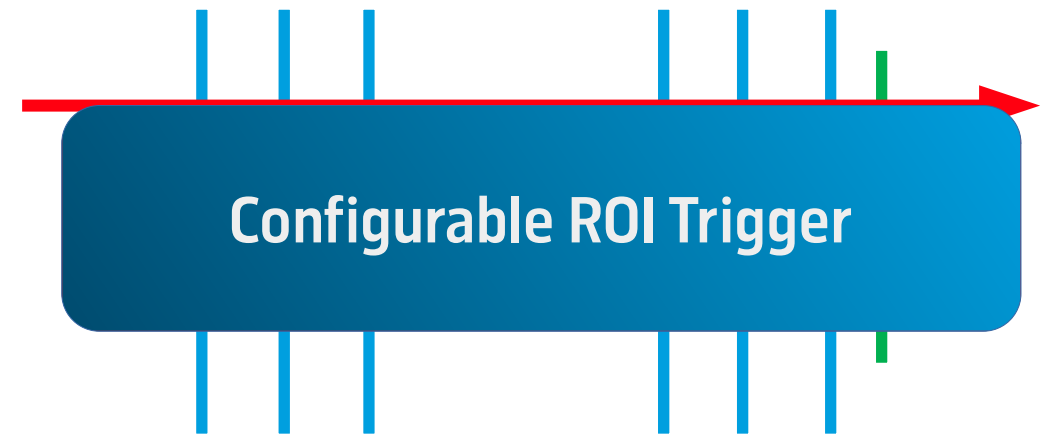


Slow telescope readout & high particle rates



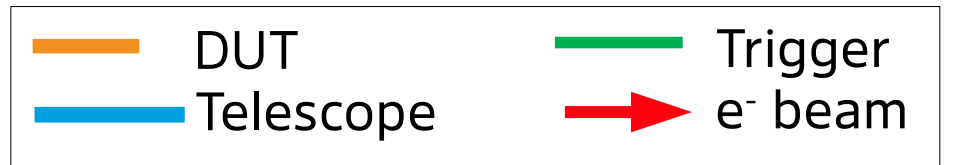
Multiple tracks within one readout
→ Impossible to associate which track belongs to which trigger

Mismatch in trigger and DUT size



Trigger on uninteresting events
→ Inefficient data taking

Timing and ROI Triggering Plane



Slow telescope readout & high particle rates

Mismatch in trigger and DUT size



TelePix2

Multiple tracks within one readout
→ Impossible to associate which track belongs to which trigger

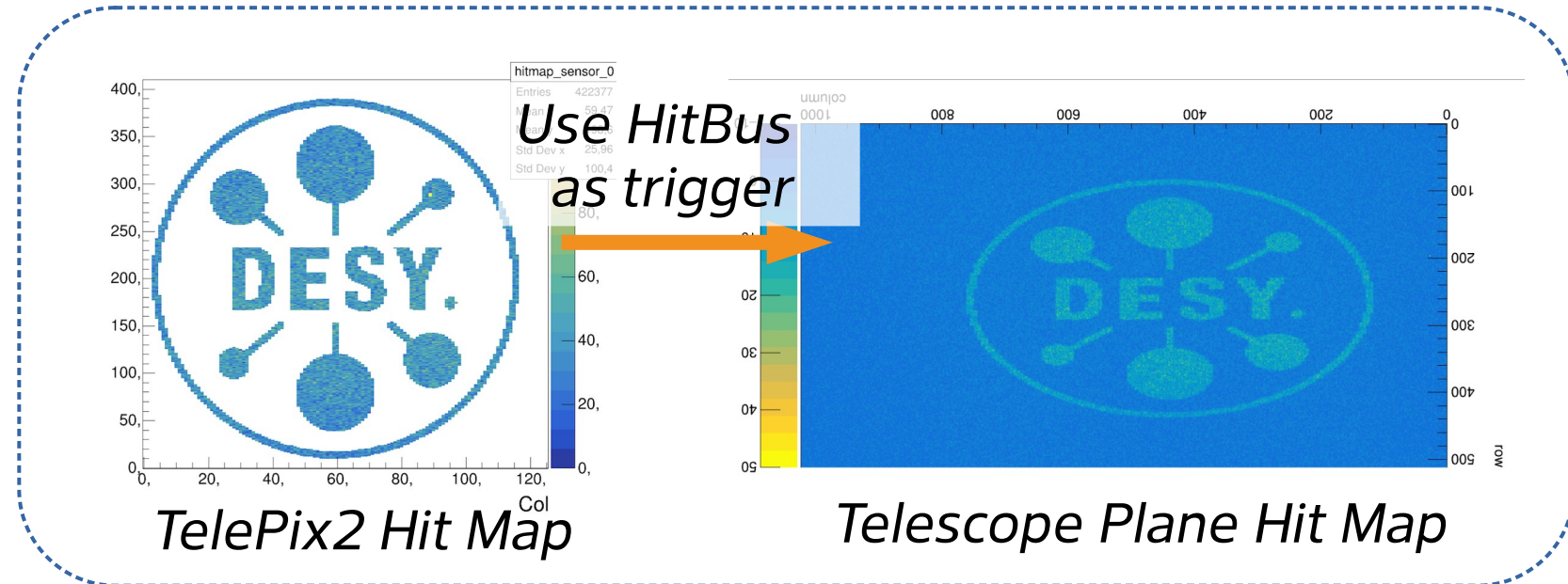
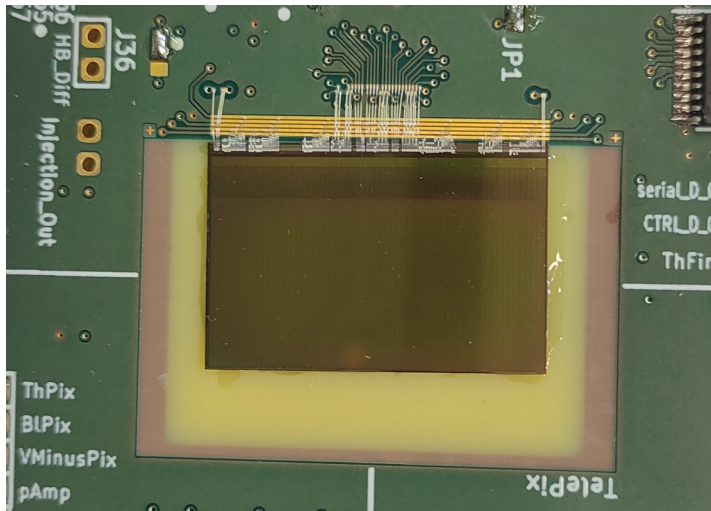
Trigger on uninteresting events
→ Inefficient data taking

TelePix2

Key Features

- **HVMAPS** sensor with a **fine timestamp (4 ns)**
- Fast output for a **user-configurable ROI trigger** (HitBus)
- A **low material budget** (0.0011 from 100 μm silicon)

Pixel Size: 165 x 25 μm
Columns x Row: 120 x 400
Chip size: 20.015 x 13.130 mm



Work in Progress

Preliminary

All the following results are preliminary, the analysis is a work in progress and results might still change.

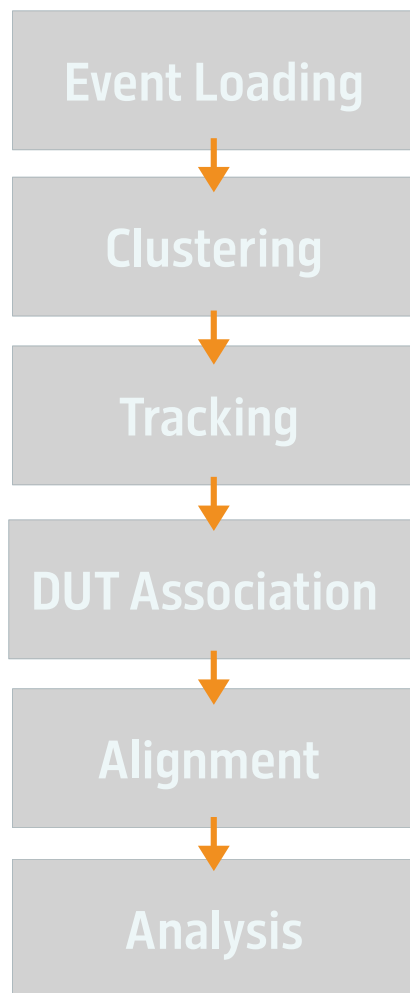
Data was taken from a test beam at the DESY II test beam facility (area 22 beam energy 4 GeV) carried out in October 2023.

Another alignment, systematic checking of various cuts, is still being carried out.



Analysis Flow

Test beam analysis and reconstruction



Use of Corryvreckan in analysis

- Very flexible, modular and configurable, open source and free to use

Data is grouped into events, then passed through a reconstruction chain

Configuration file:

- Which modules with what parameters and order

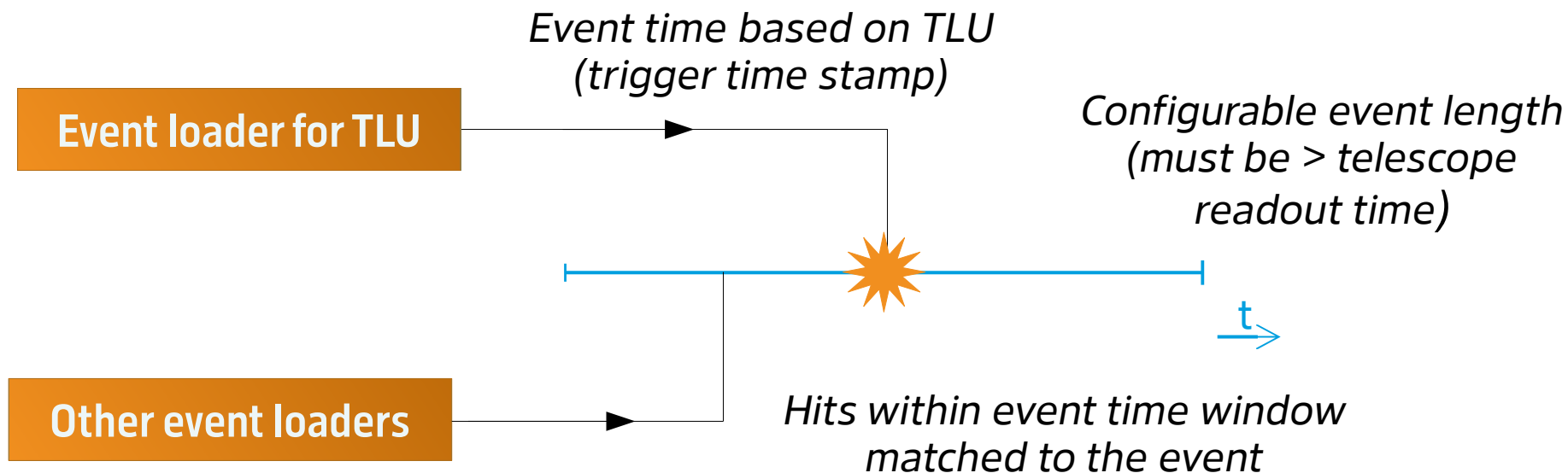
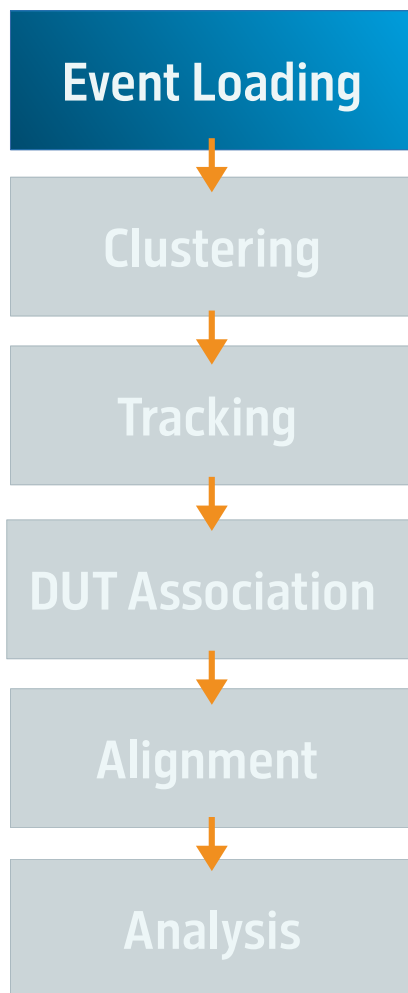
Geometry file:

- Relative positions & rotation of sensors

Corryvreckan Paper: [D. Dannheim et al 2021 JINST 16 P03008](#)

Event Loader

Event definition



Merged TelePix2 data-driven readout with triggered readout of telescope

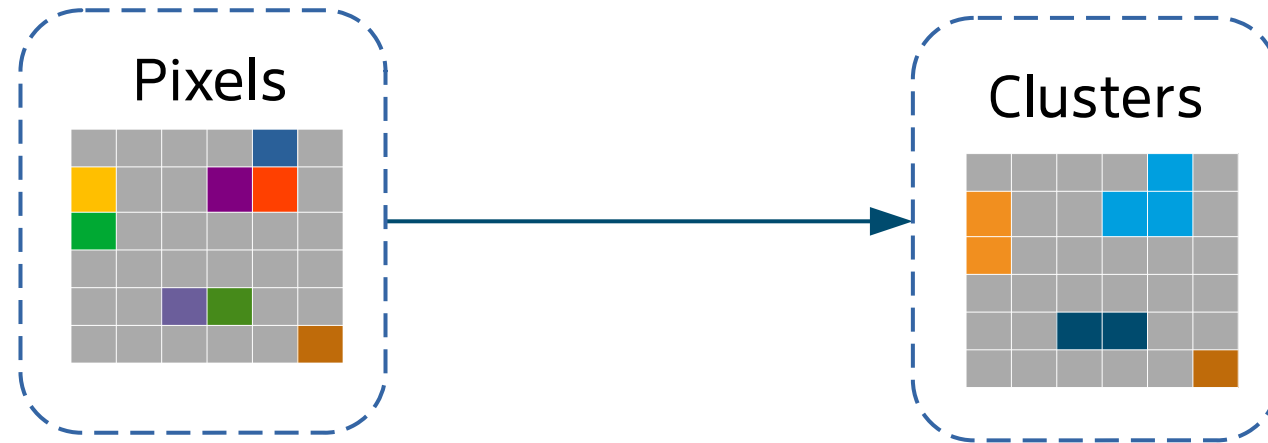
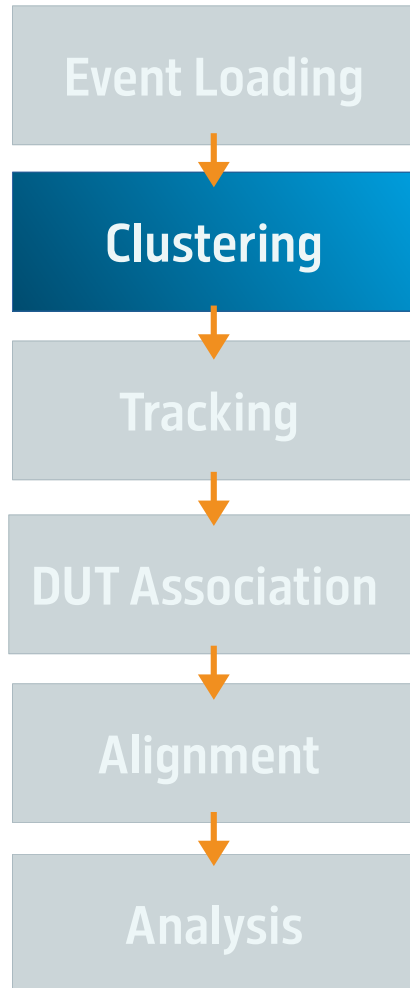


Specific event loaders include:

- [EventLoaderEUDAQ2](#) for telescope data and TLU data
- [EventLoaderMuPixTelescope](#) for TelePix data and any data recorded with the HV-MAPS DAQ of Heidelberg

Clustering

Pixels to Clusters



Group **nearest neighbors** together

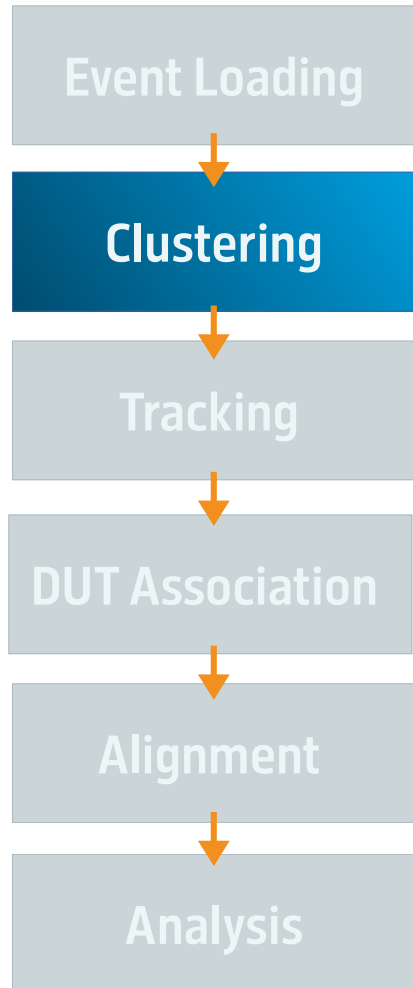
- Can also use a time cut to improve accuracy
- Center of gravity used as hit position

Note: telescope readout slow, timestamp for the telescope clusters must come from the trigger time stamp

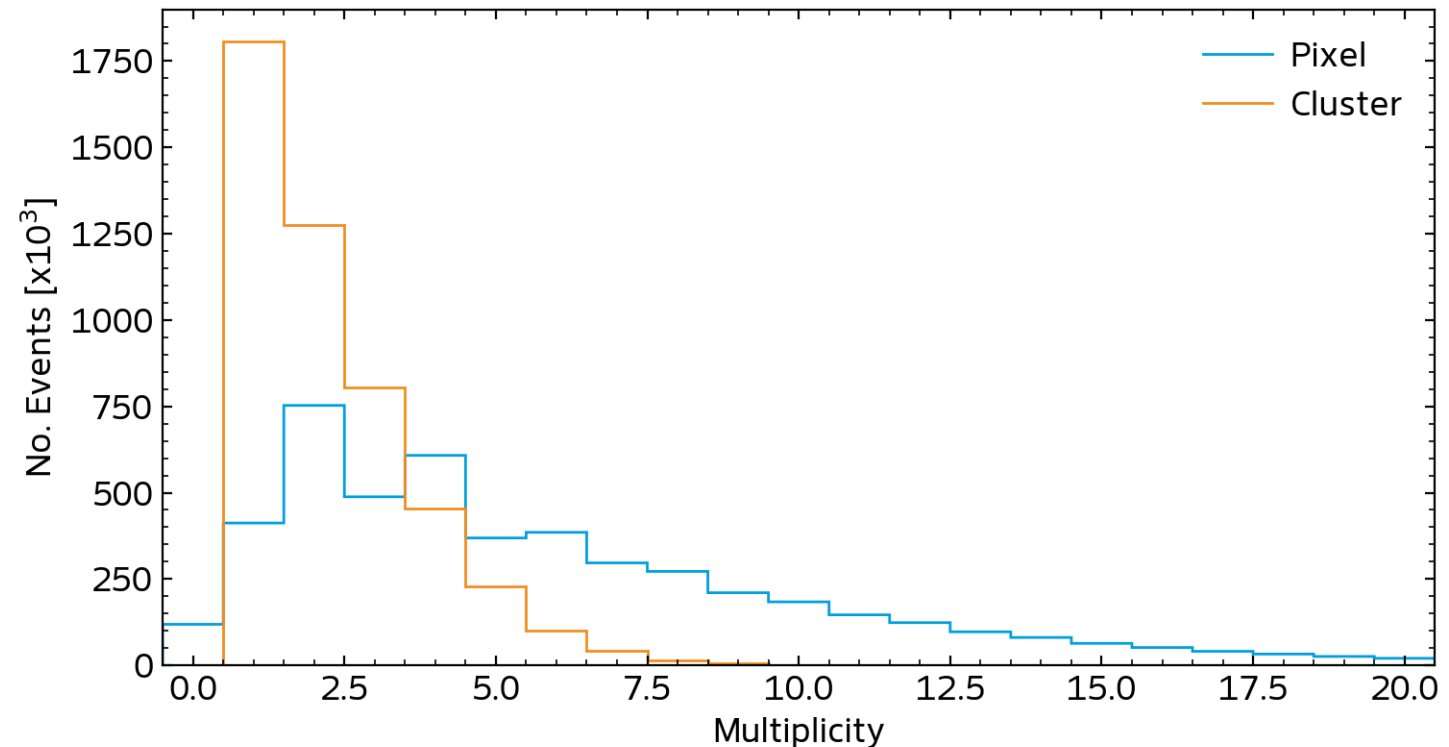
Modules used here are *ClusteringSpatial* and *Clustering4D*

Clustering

Pixels to Clusters



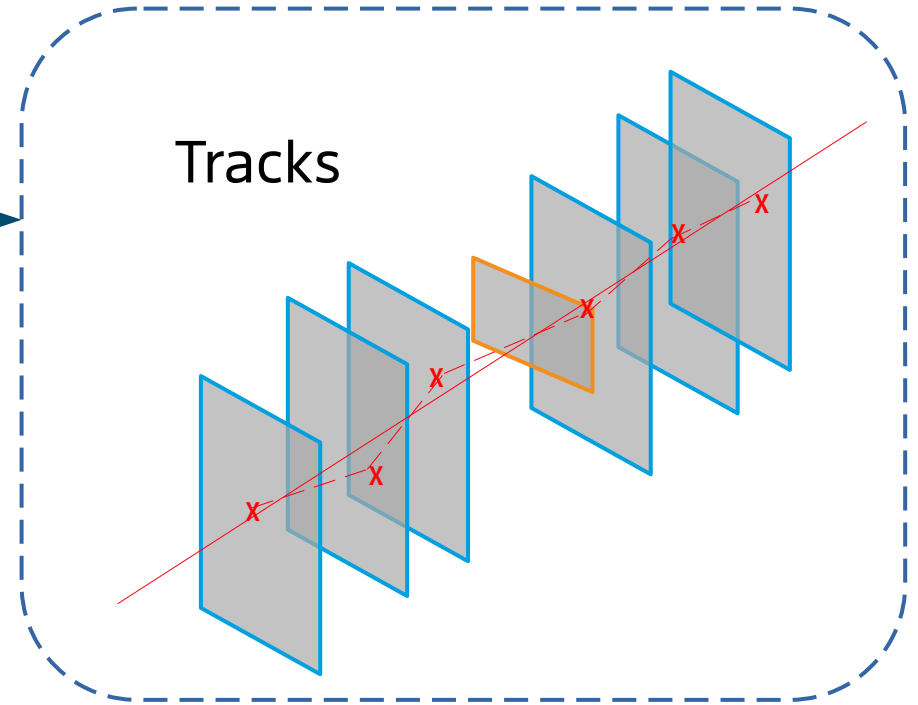
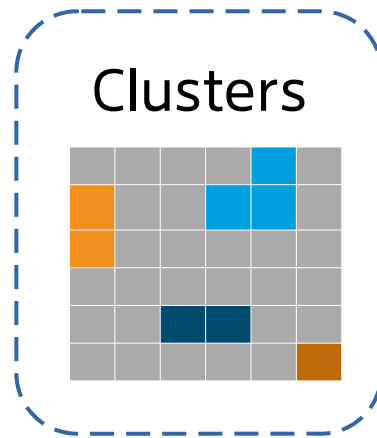
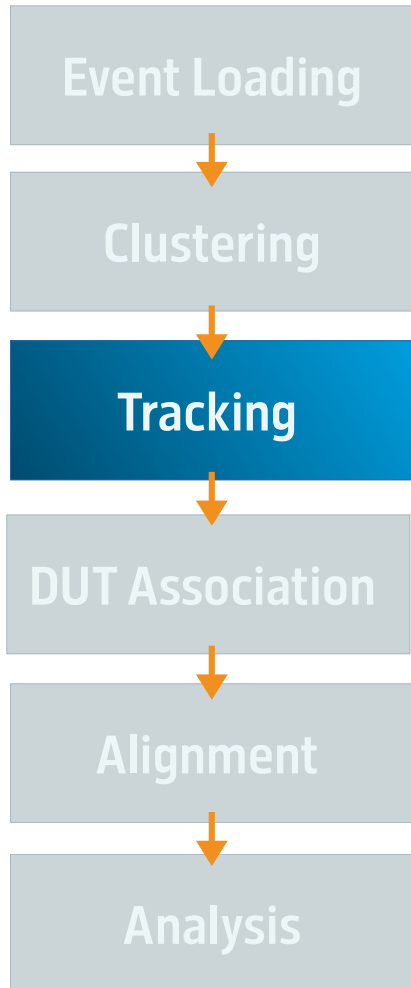
Comparison of no. pixels hit and no. clusters per event for 1st Adenium plane



Pixel Multiplicity > Cluster Multiplicity
→ Effective clustering

Tracking

Clusters to Tracks



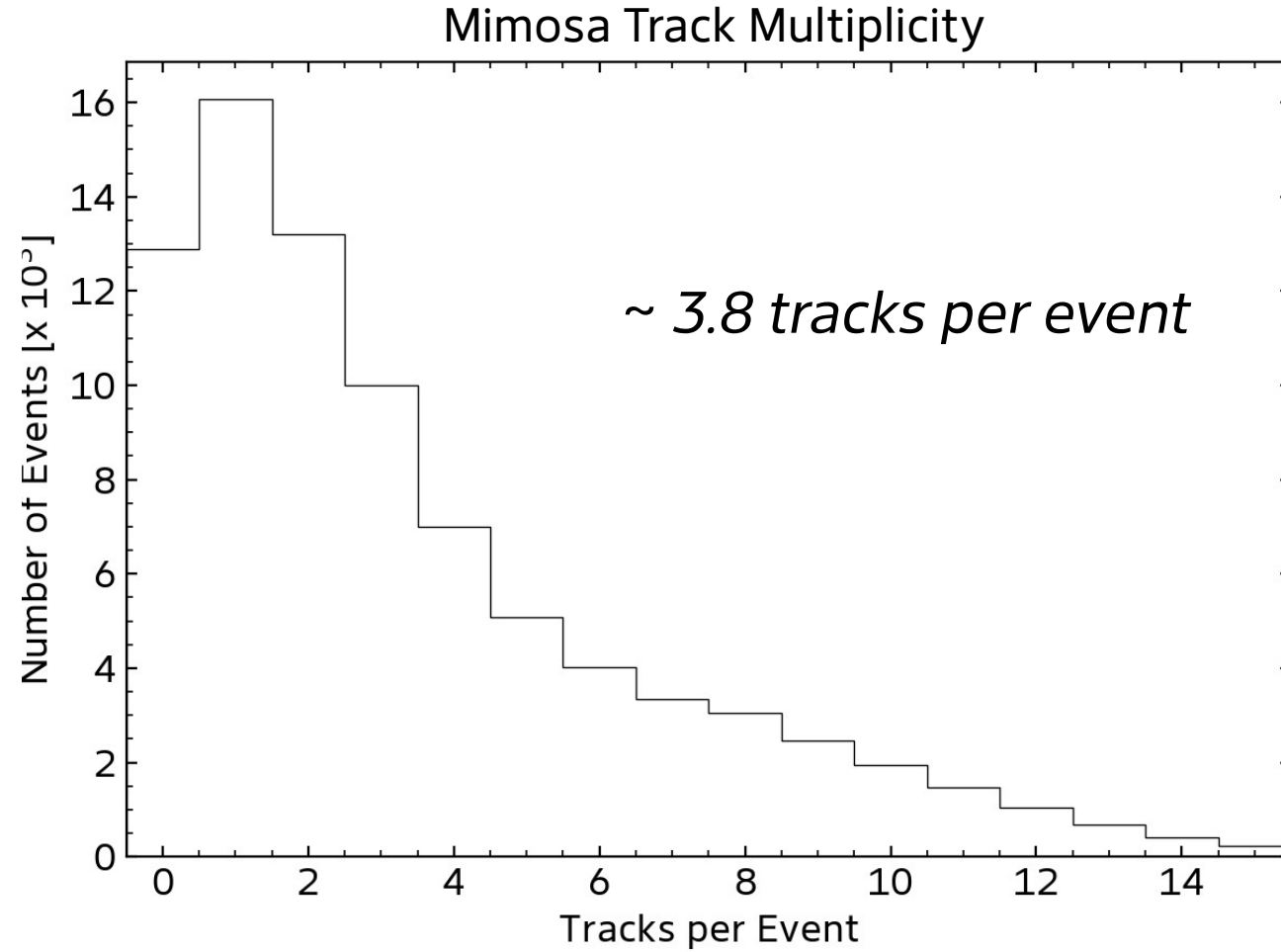
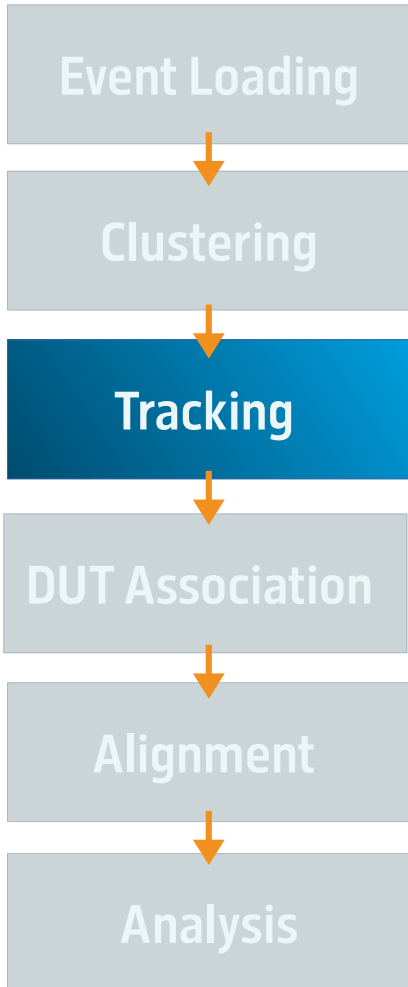
Connect clusters in different planes into one track.

- Here using General Broken Lines (GBL) model: **allows for scattering at planes and in the air between.**
- Now able to calculate **track intersection** with the DUT

Module used here is *Tracking4D*

Tracking

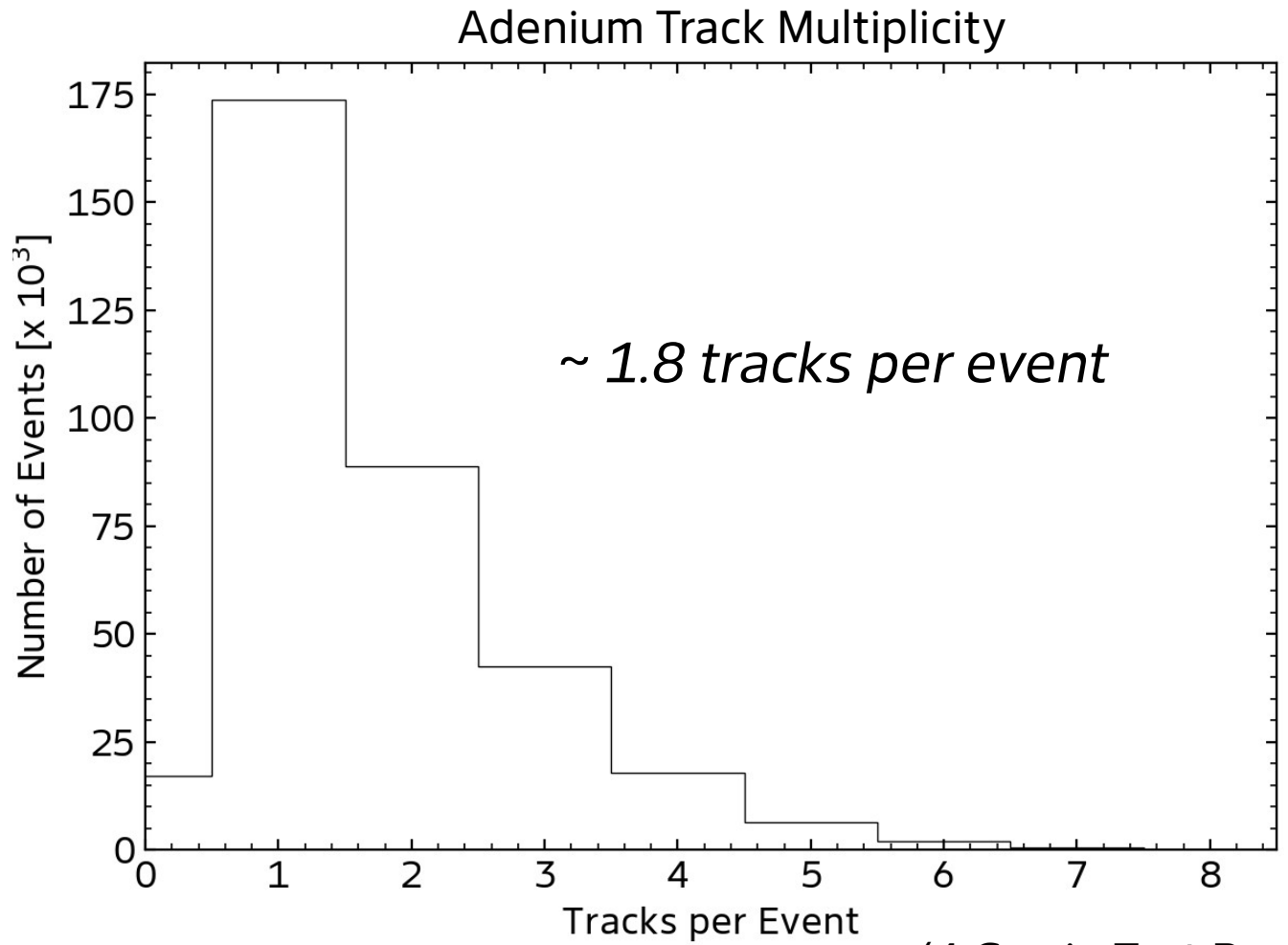
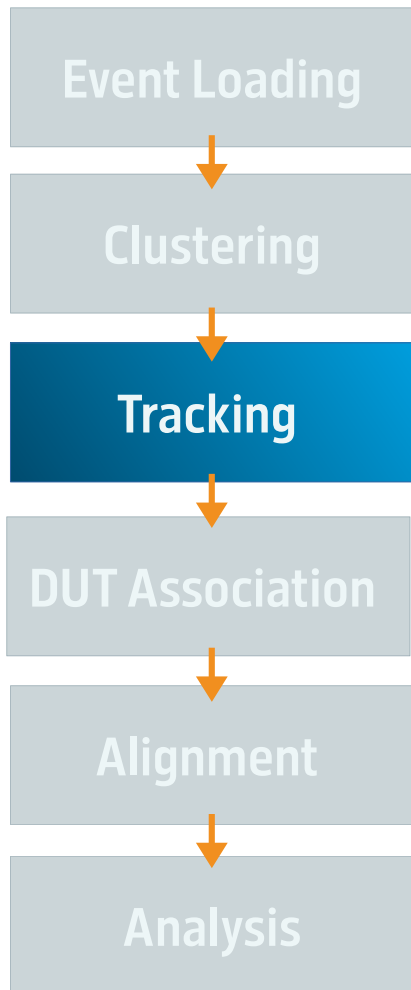
Clusters to Tracks



(3 GeV in Test Beam area 21)

Tracking

Clusters to Tracks

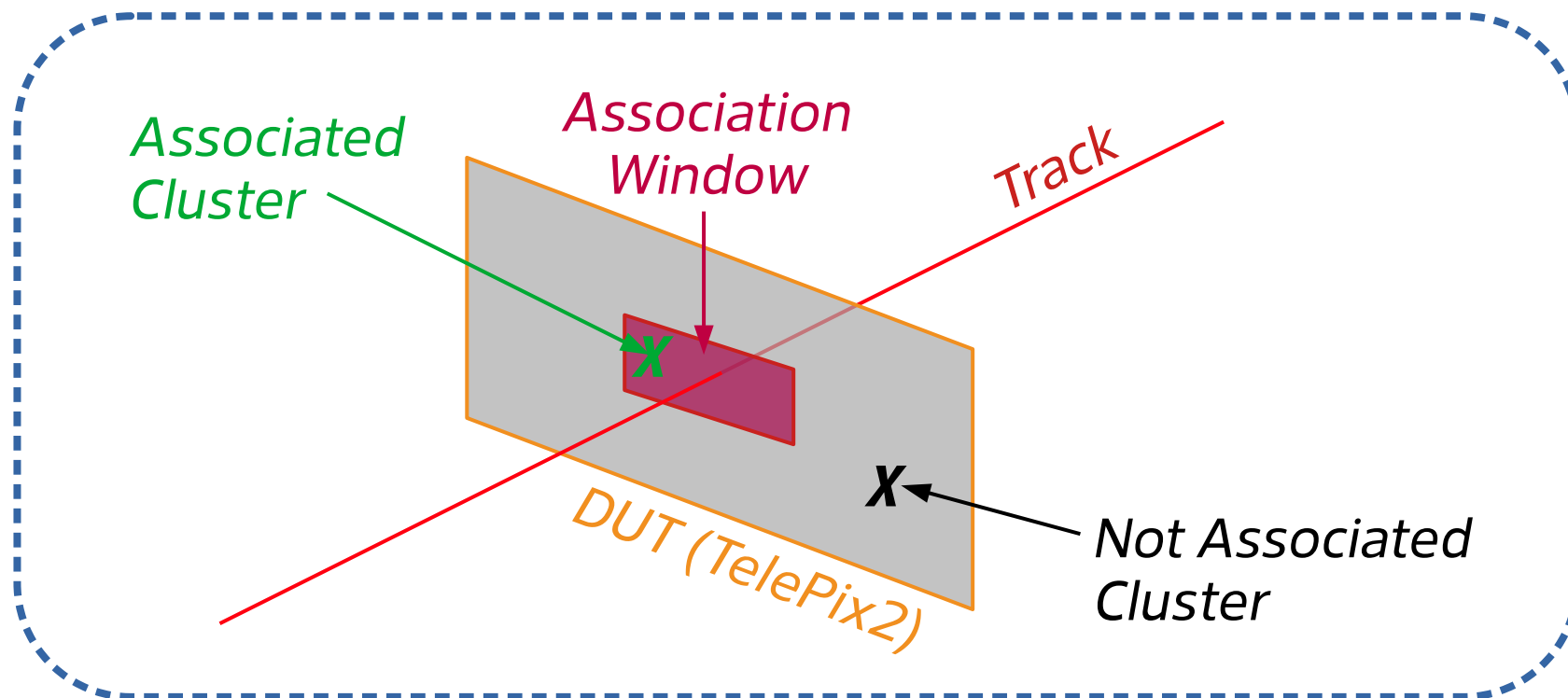
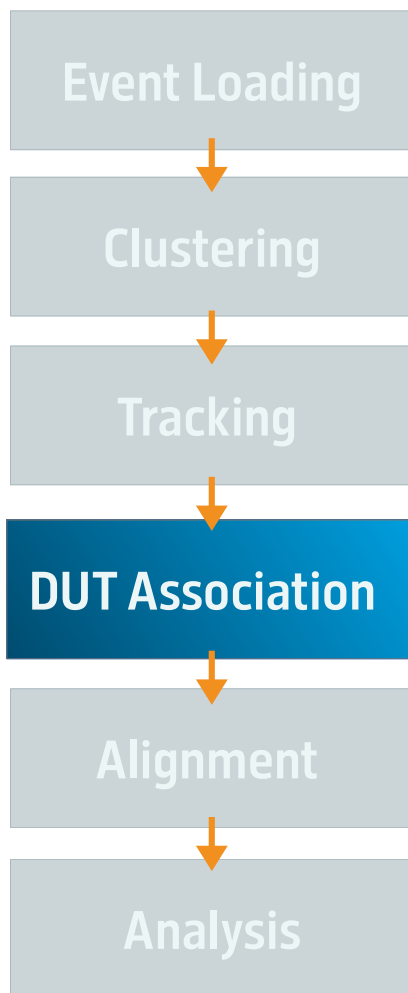


(4 Gev in Test Beam area 22)

Subsequent analysis filtered to 1 track per event

DUT Association

Matching DUT Hits to Telescope Tracks

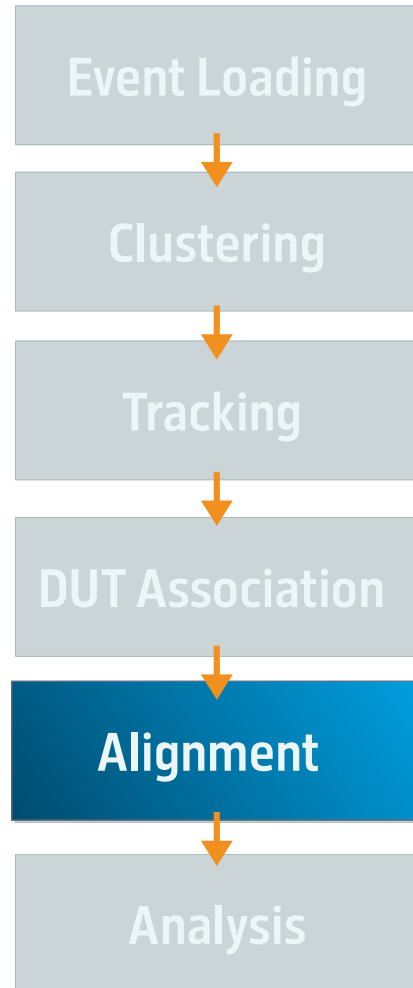


If the **DUT cluster** lies within a **spatial and time window** of the track intersection
→ associate this cluster with the track

Module used here is *DUTAssociation*

Alignment

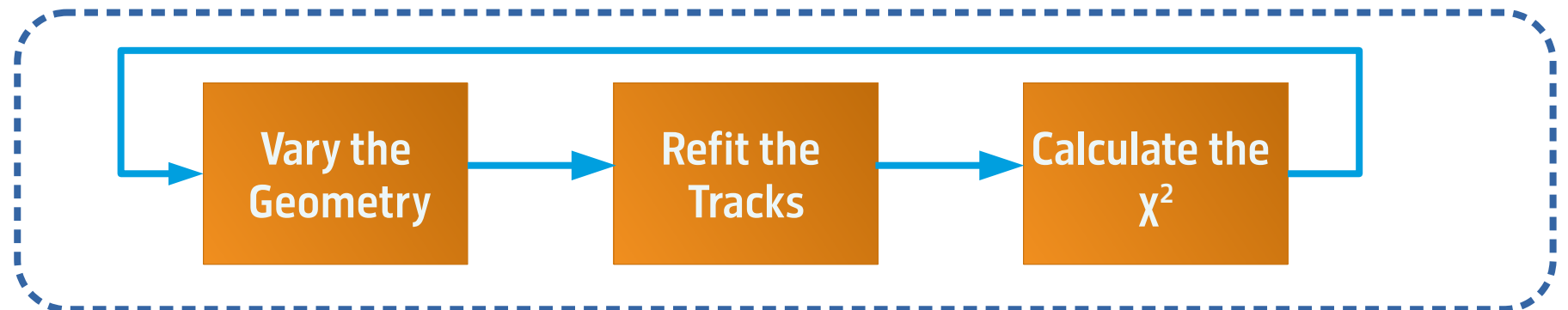
Matching Physical Position



Difficult to **match measured geometry** in geometry file with the **precise physical locations**.

→ Rely on alignment modules to instead precisely align sensors

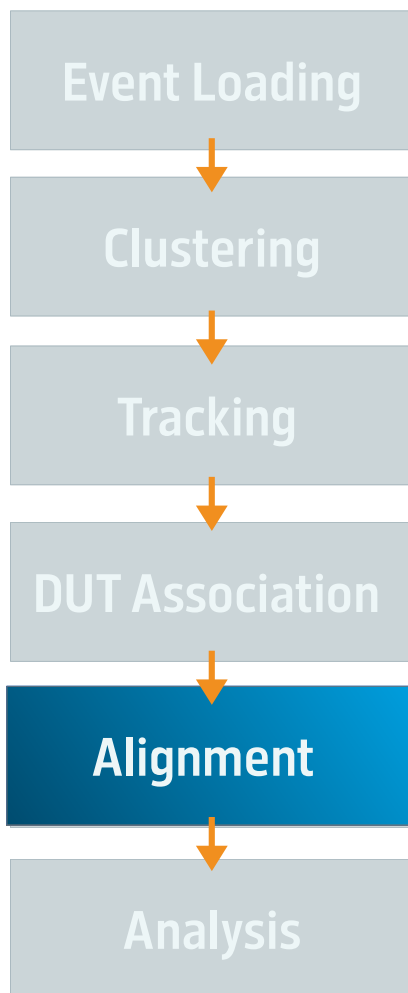
Iteratively adjust geometry (position and rotation) to **minimise the total χ^2 of the track**. Minimiser is TMinuit2 based.



*Carried out separately for Telescope (Adenium) with **AlignmentTrackChi2** and DUT (TelePix) **AlignmentDUTResidual***

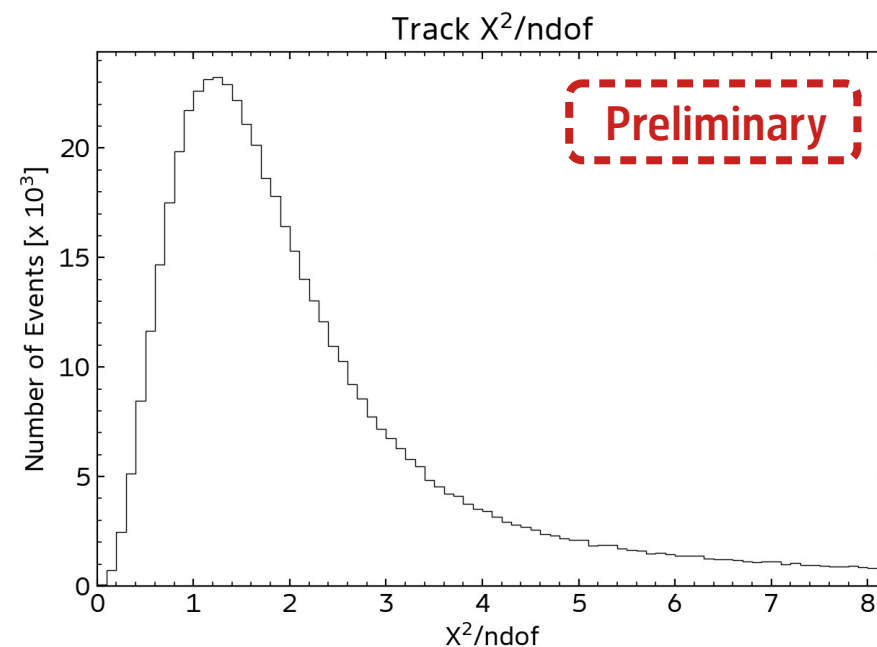
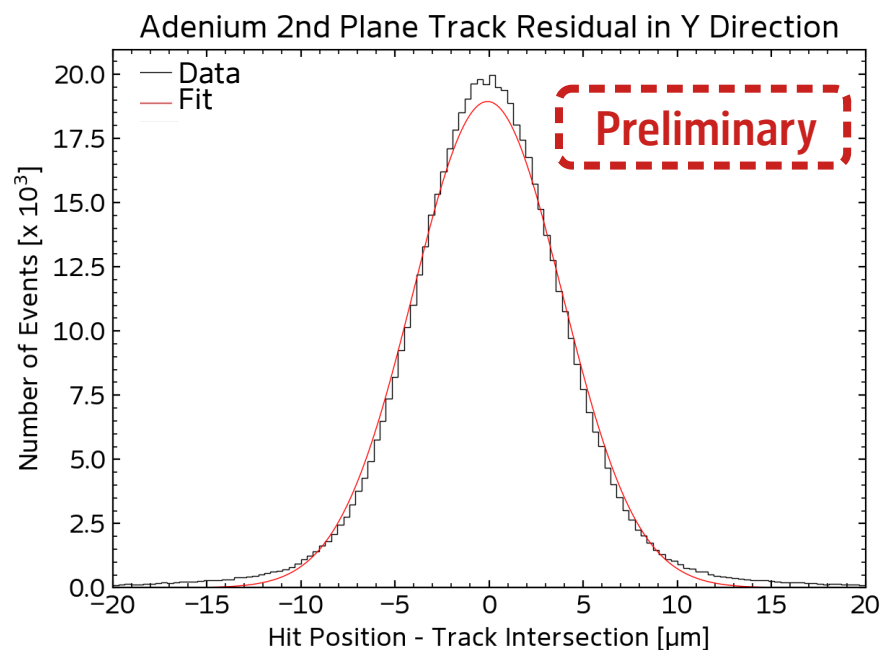
Alignment

Matching Physical Position



A good alignment results in:

- Track residuals centered around 0 μm
- A χ^2 divided by the number of degrees of freedom peaking around 1.

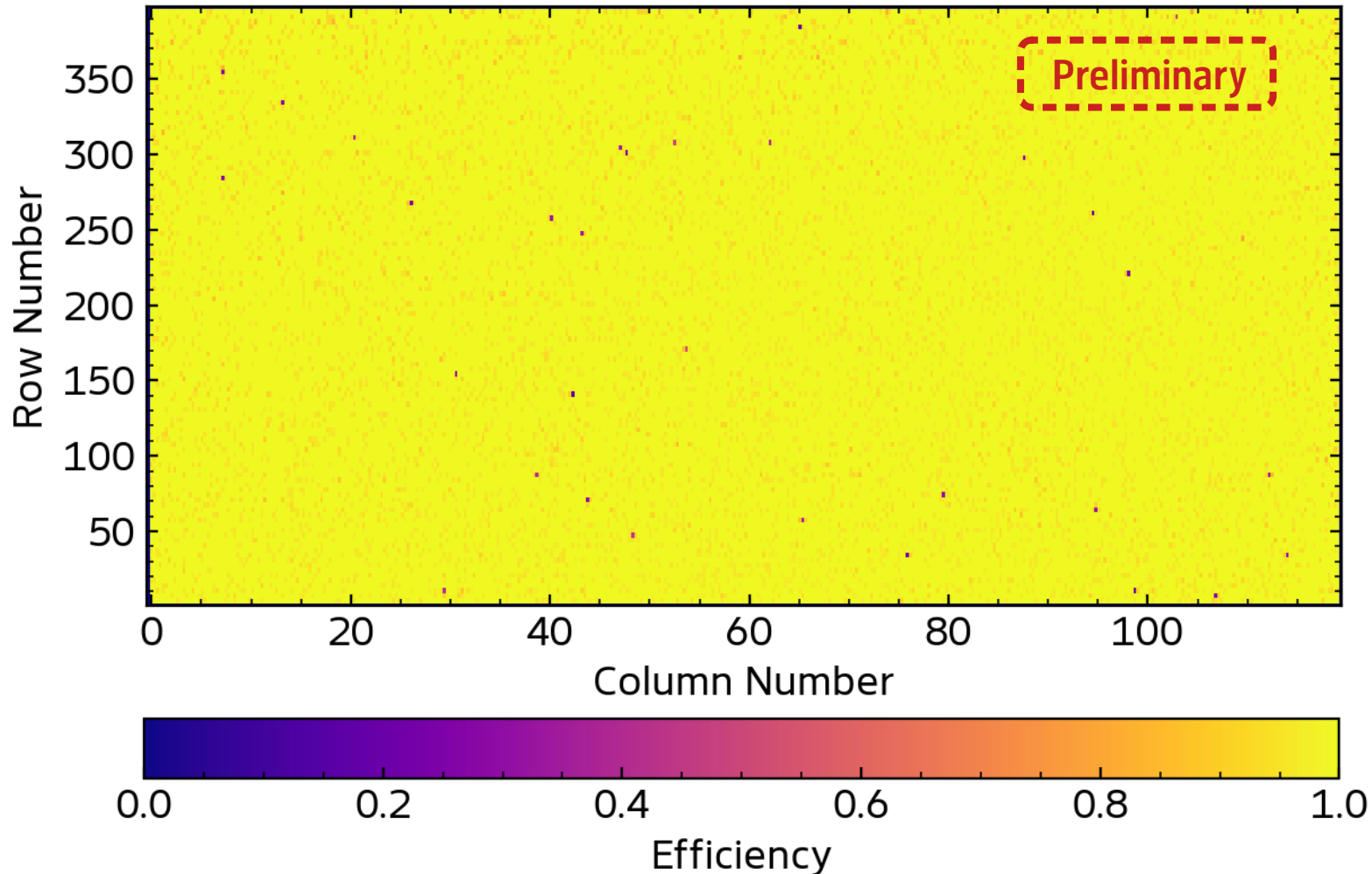


Efficiency

$$\text{Efficiency} = \frac{\text{Tracks with an Associated DUT Hit}}{\text{Tracks that intersect the DUT}}$$

* Statistical efficiency

Chip Efficiency

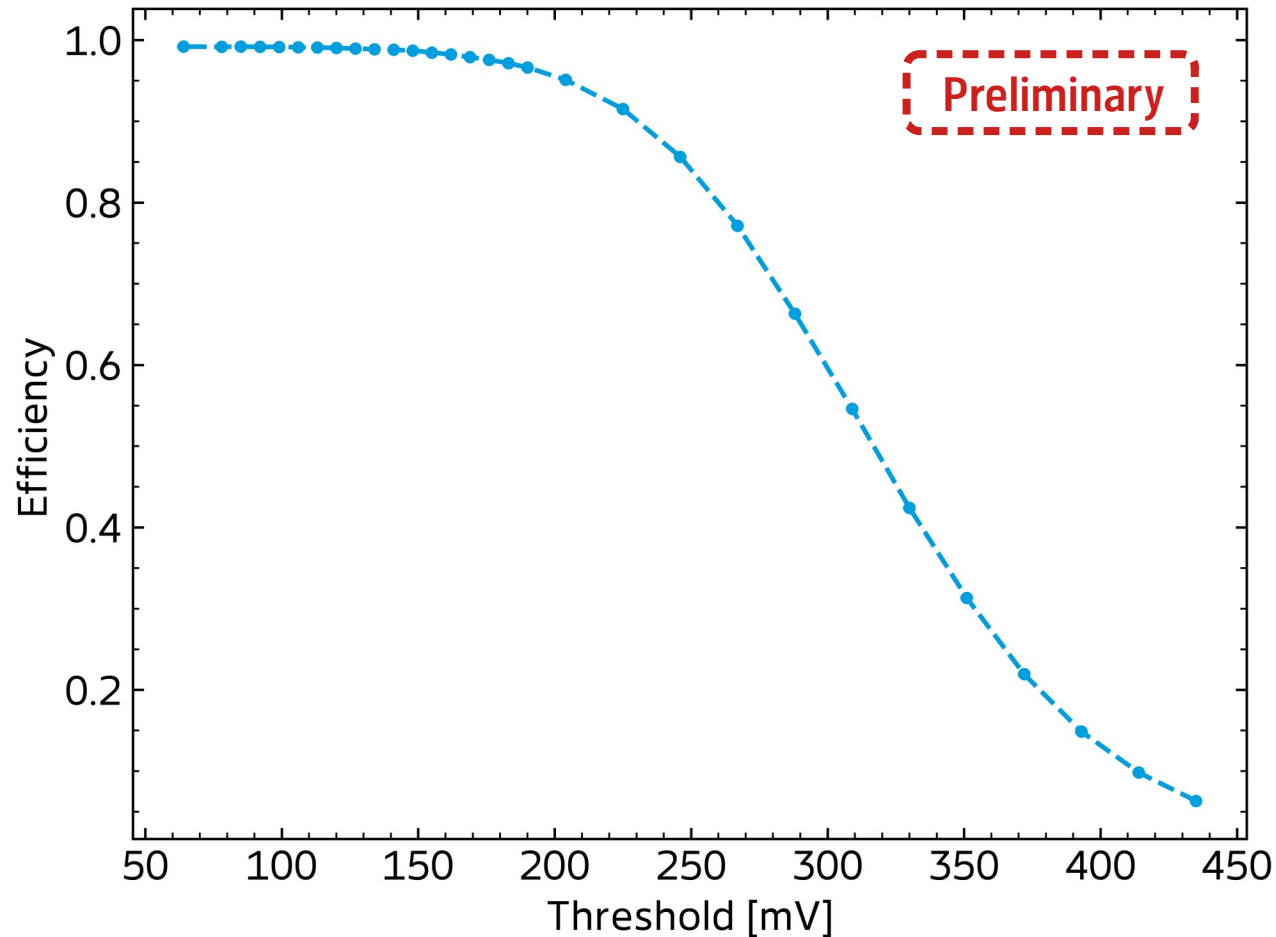


At a bias of 85 V
& a threshold of 57 mV

**Efficiency of
99.204 ± 0.008 %**

Efficiency vs Threshold

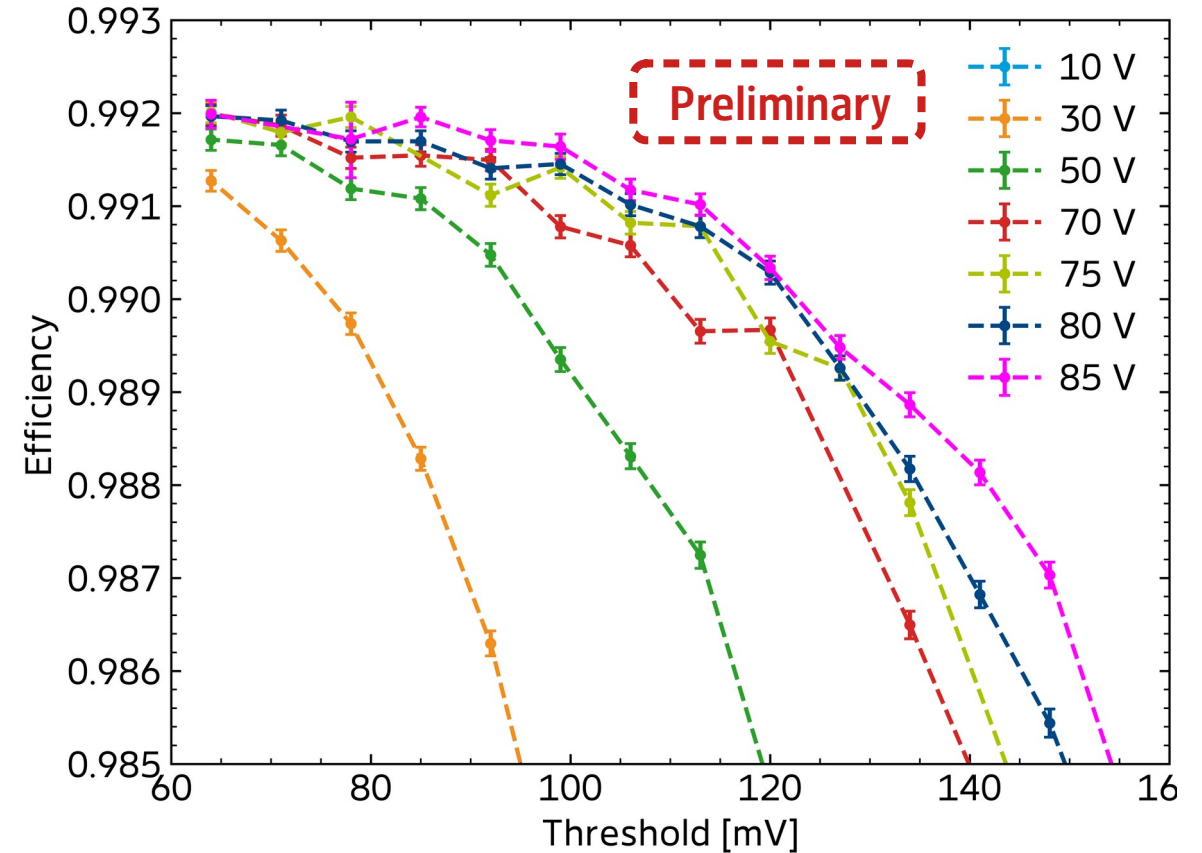
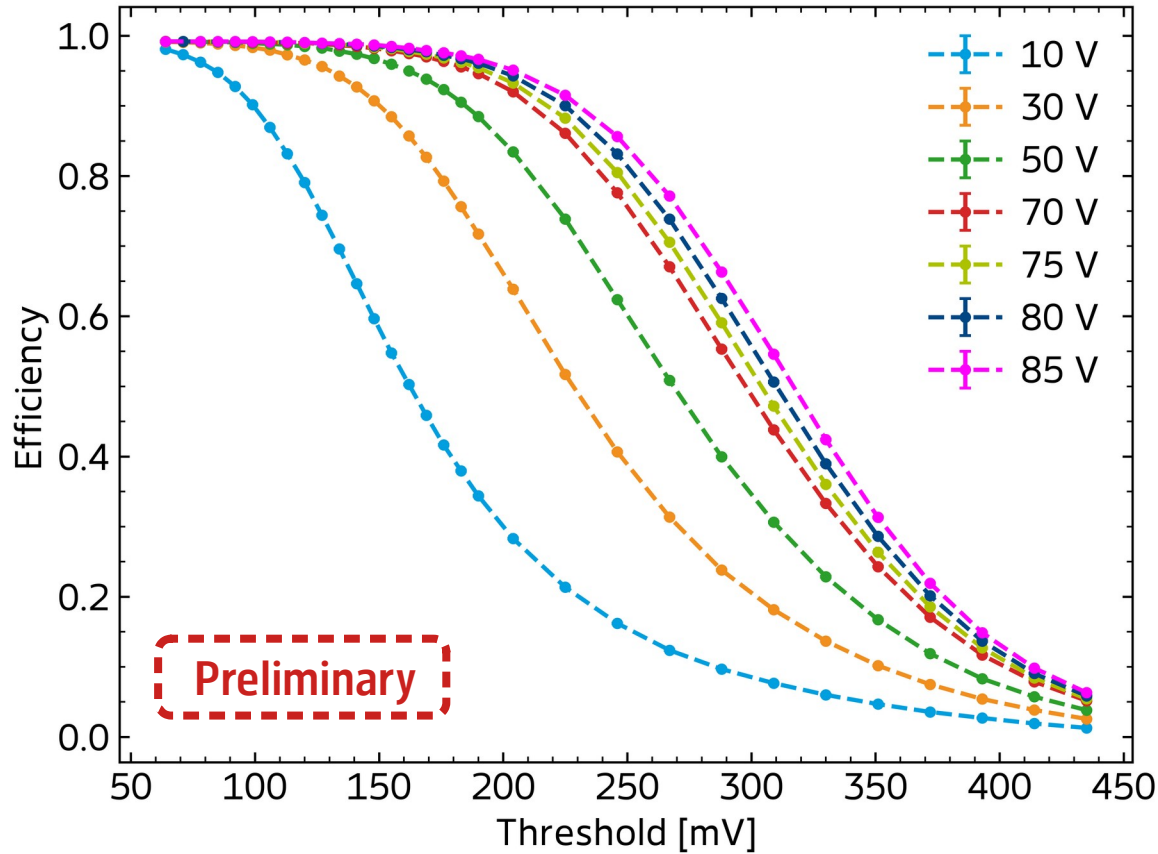
Efficiency changes with respect to threshold of pixel comparator



- Greater the plateau → Greater the suitable operating region
- Could not decrease threshold further Started to be effected by noise

Bias is at 85 V

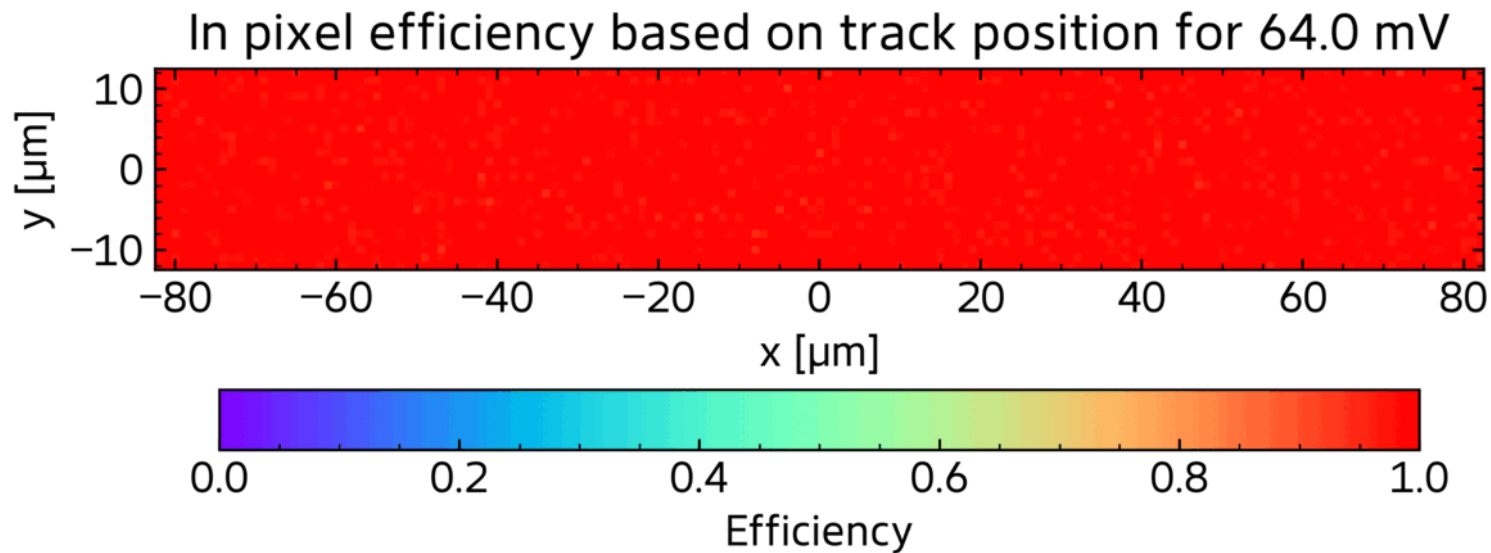
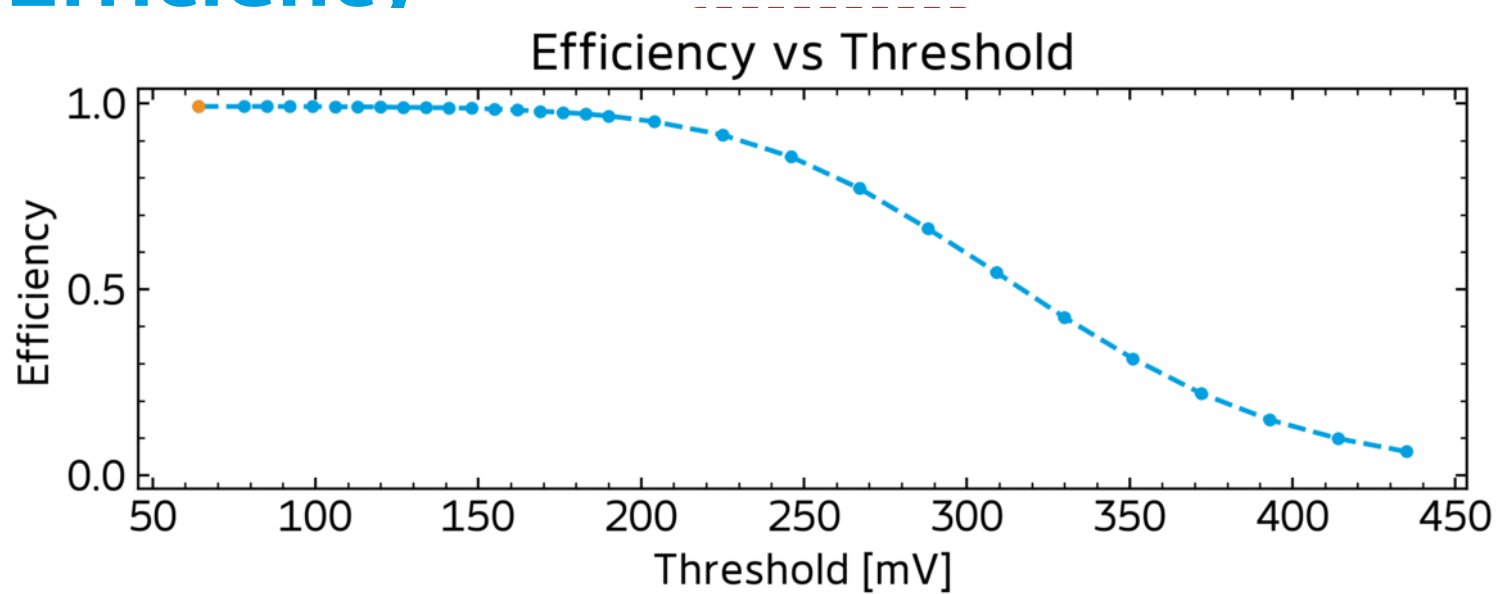
Efficiency vs Threshold for Different Voltages



Higher bias voltage \rightarrow Greater depletion region \rightarrow More charge collected

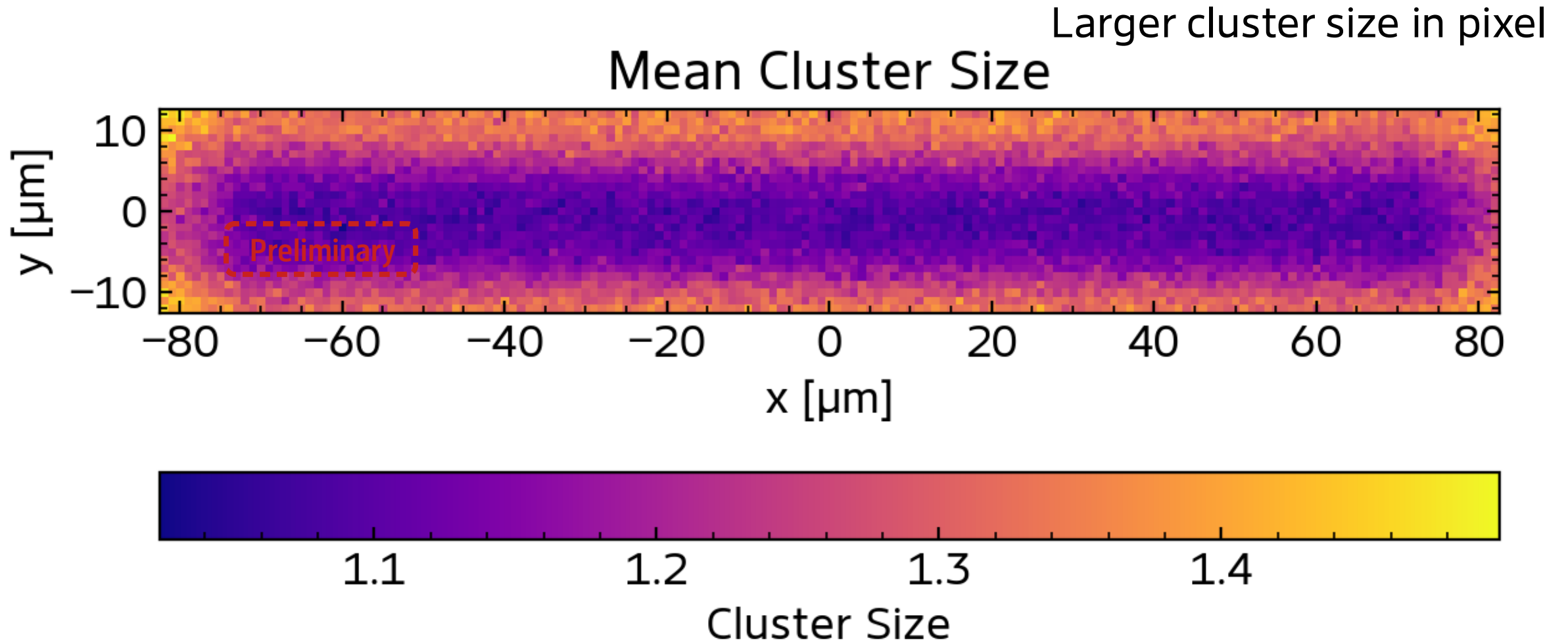
In-Pixel Efficiency

Full Pixel



At a bias of 85 V
& a threshold of 57 mV

In-Pixel Mean ClusterSize

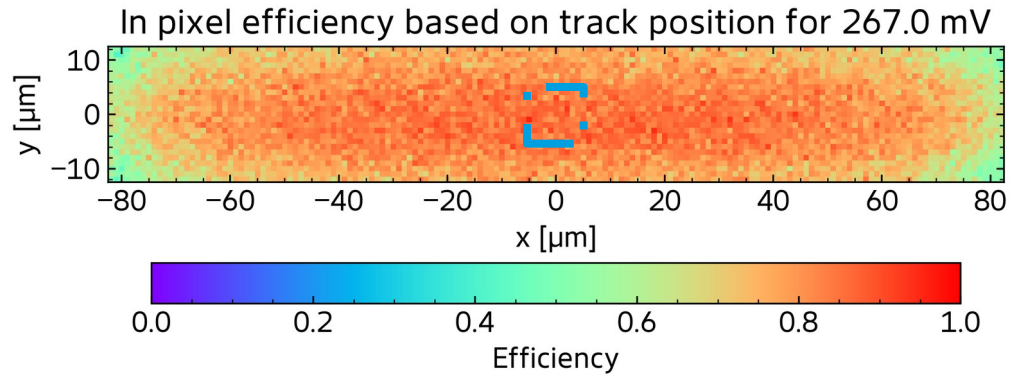


Bias 85 V and threshold 57 mV

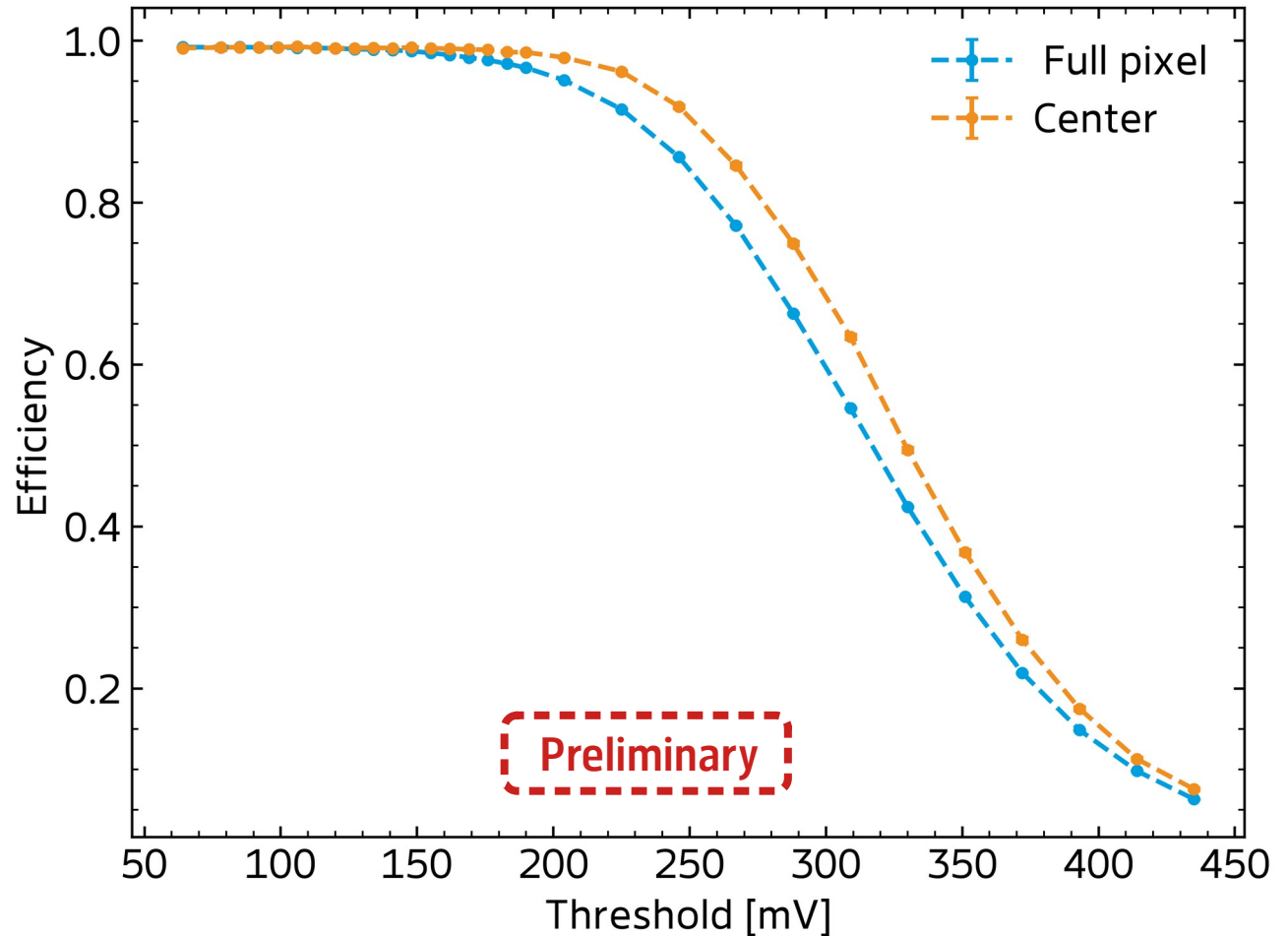
In Pixel Efficiency

Full Pixel and Center of Pixel Comparison

- Efficiency in the center $10 \times 10 \mu\text{m}$ in each pixel calculated

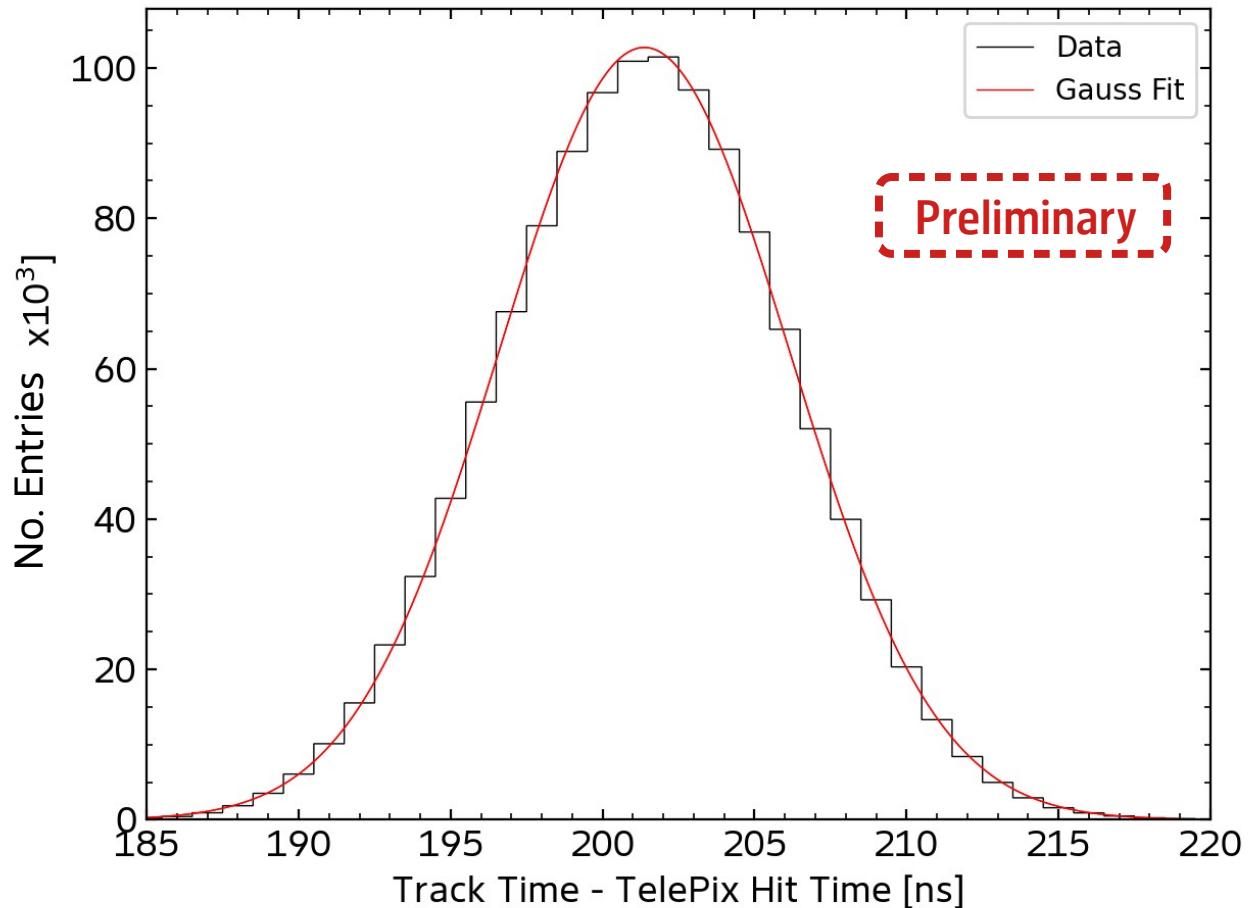


- Larger plateau when looking at center of each pixel only
- Bias of 85V



Timing Resolution

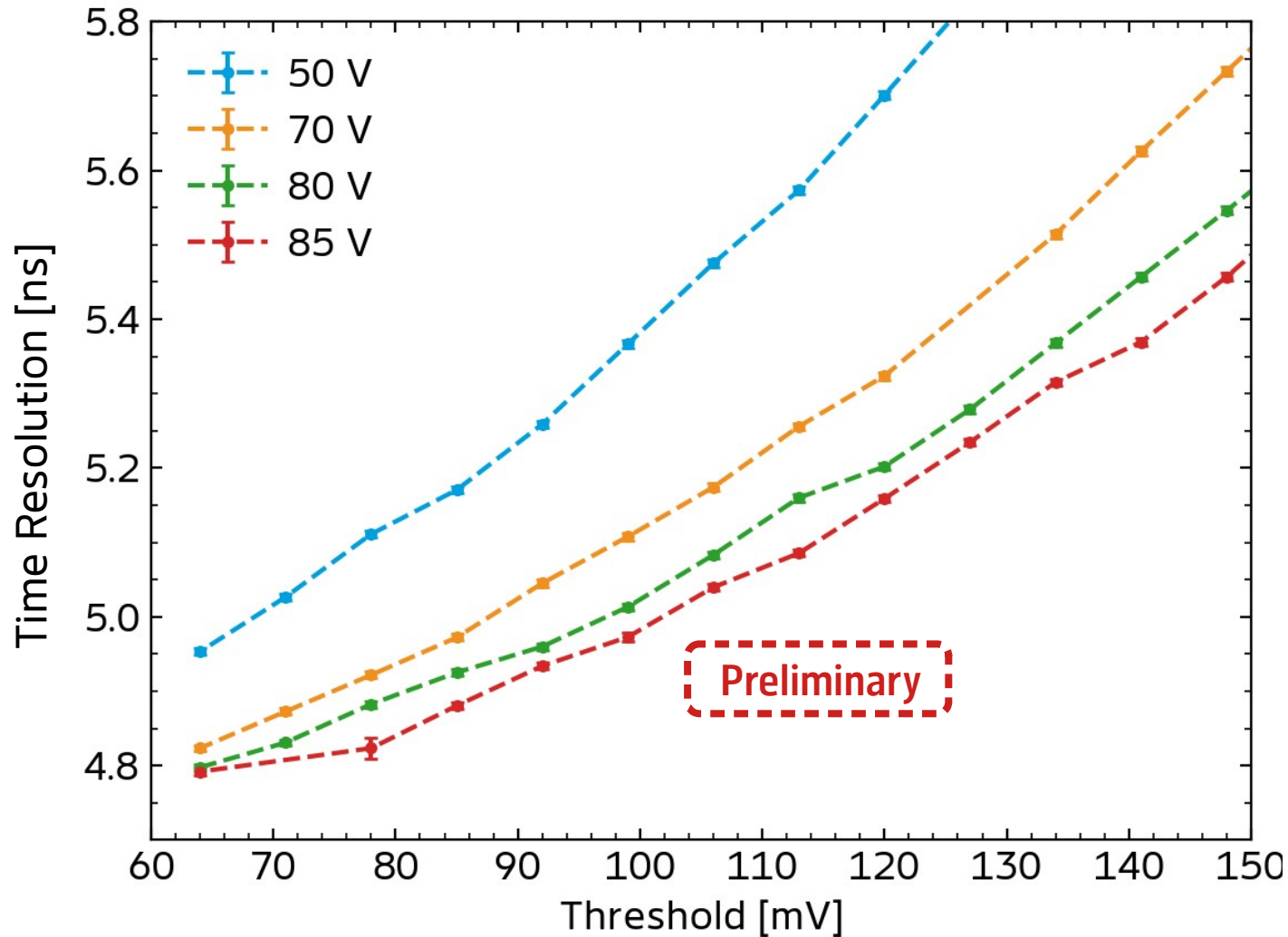
Ideal Case



Time resolution taken as the σ of a Gaussian fit of the time residual

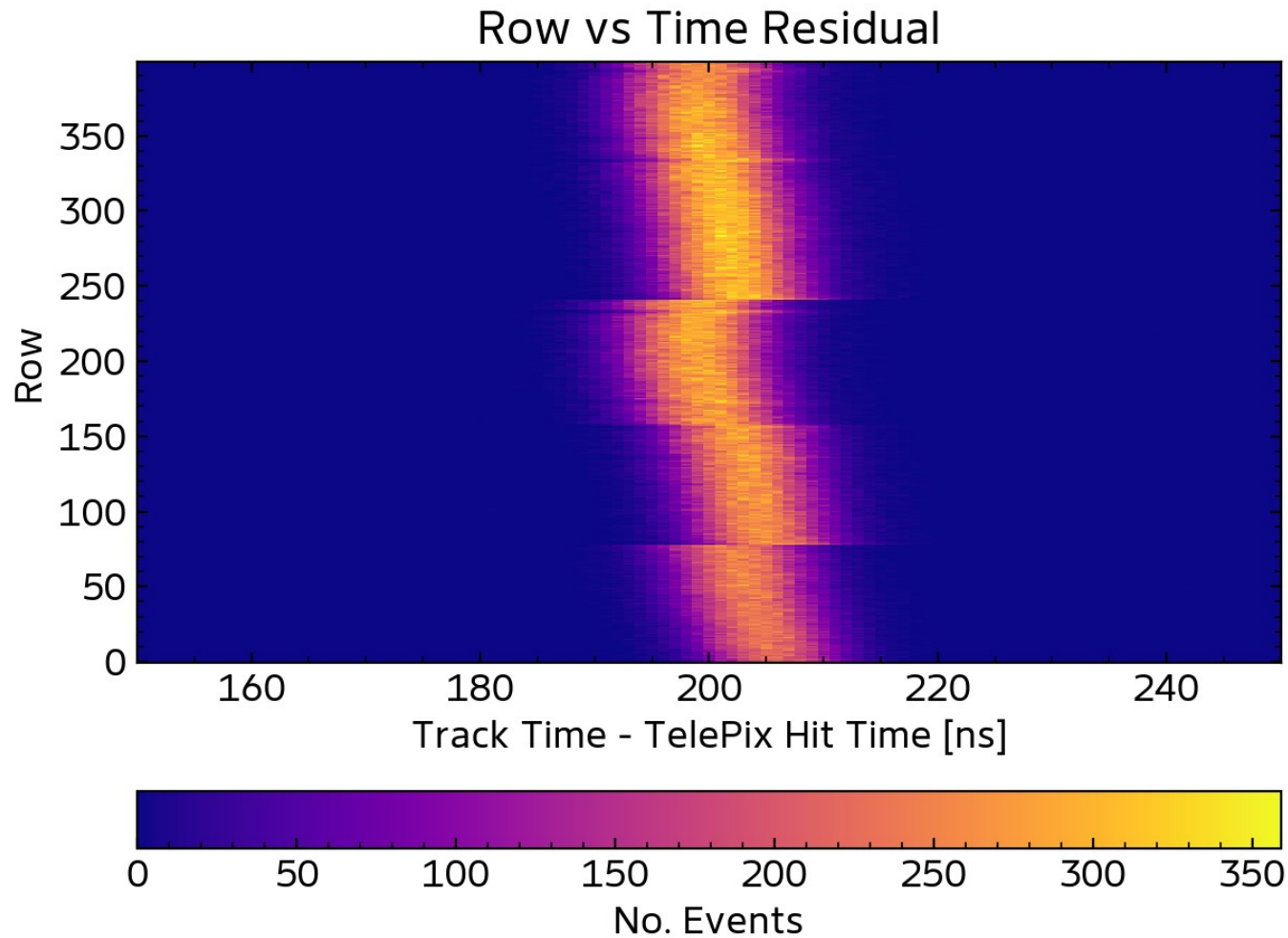
At a bias voltage of 85 V and a threshold of 57 mV a time resolution of 4.781 ± 0.003 ns.

Timing Resolution with Threshold and Voltage



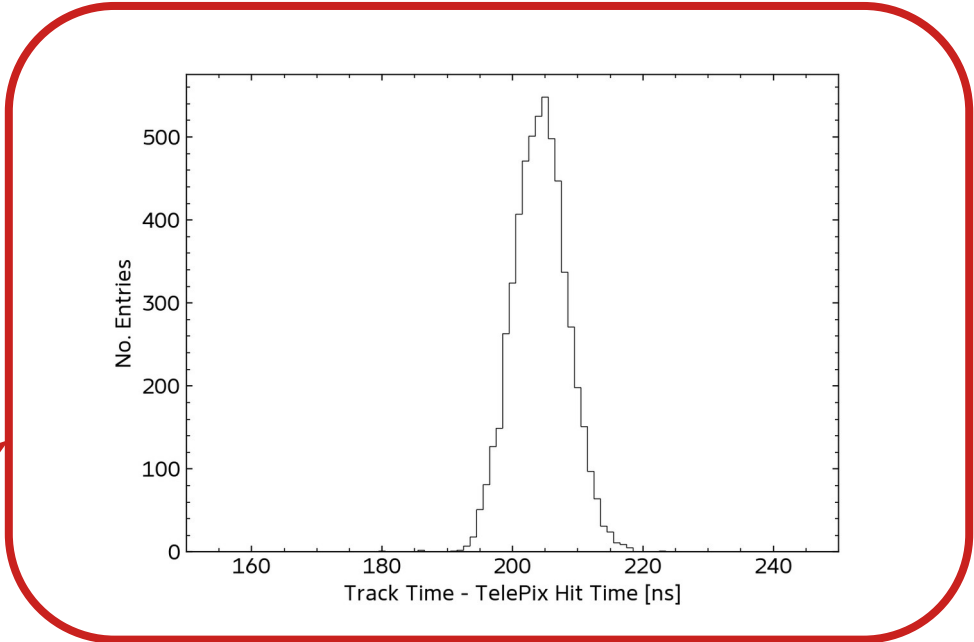
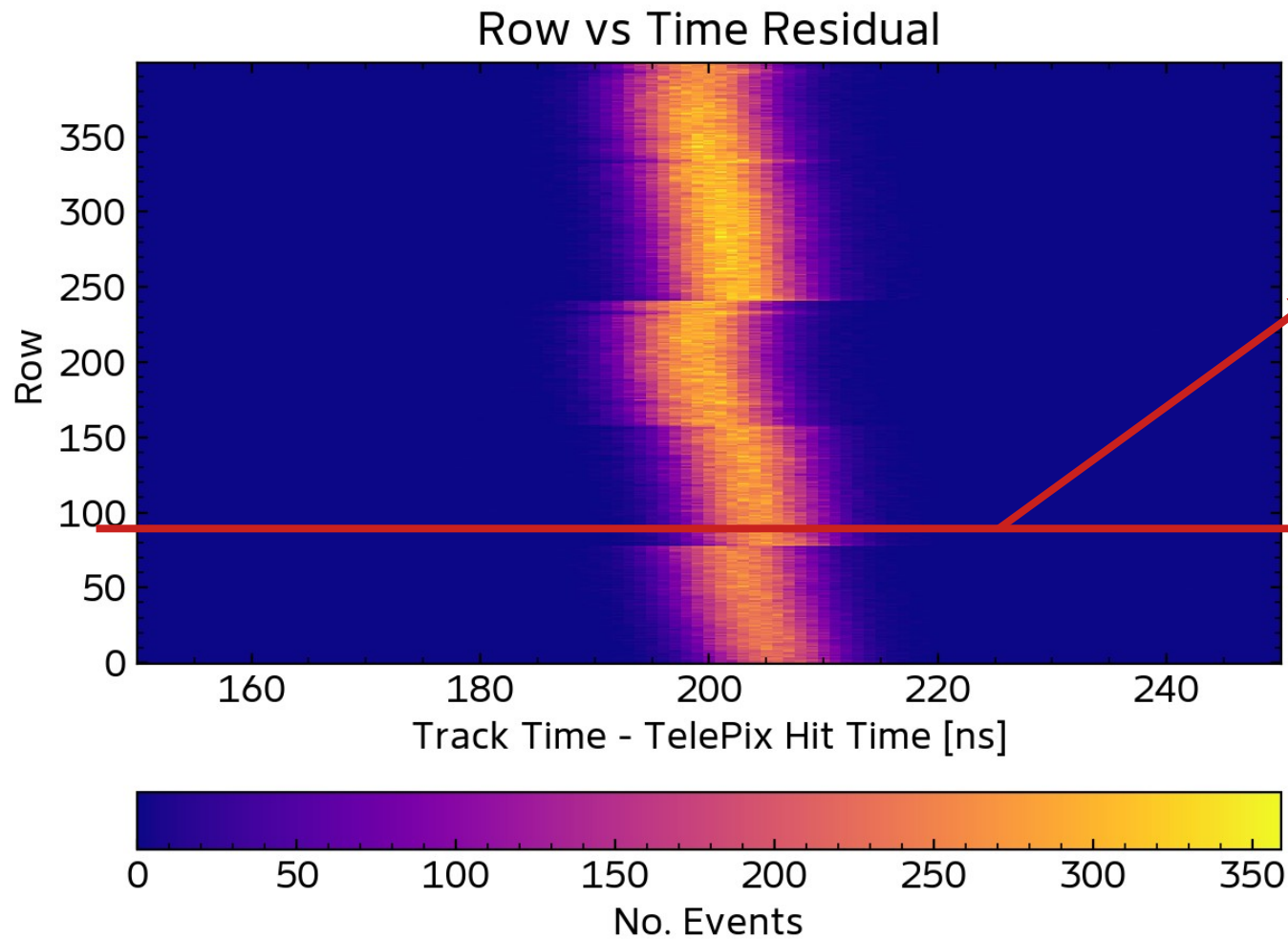
Still a benefit in time resolution with a reduction in threshold

Time Residual Corrections



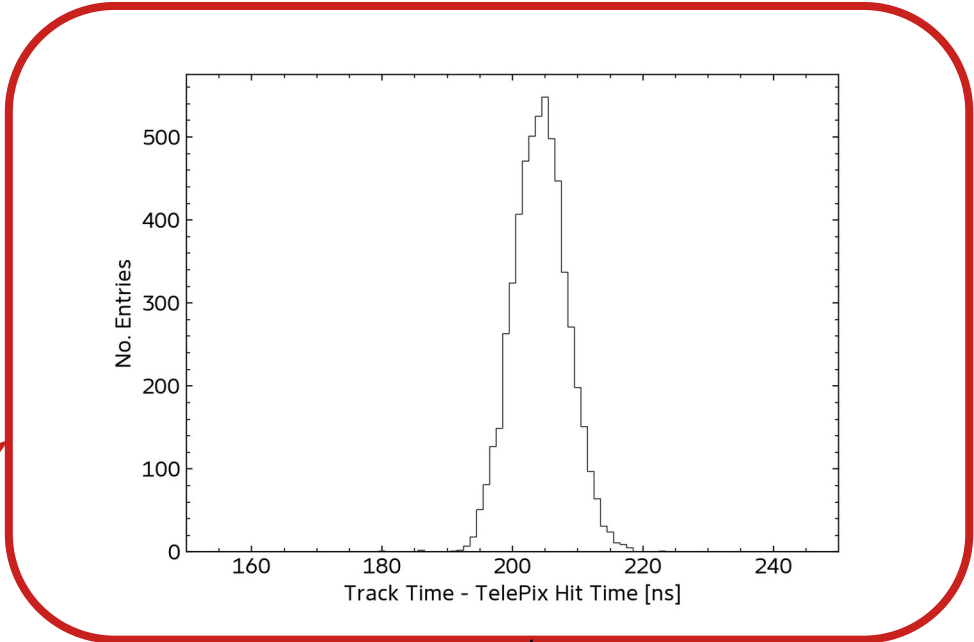
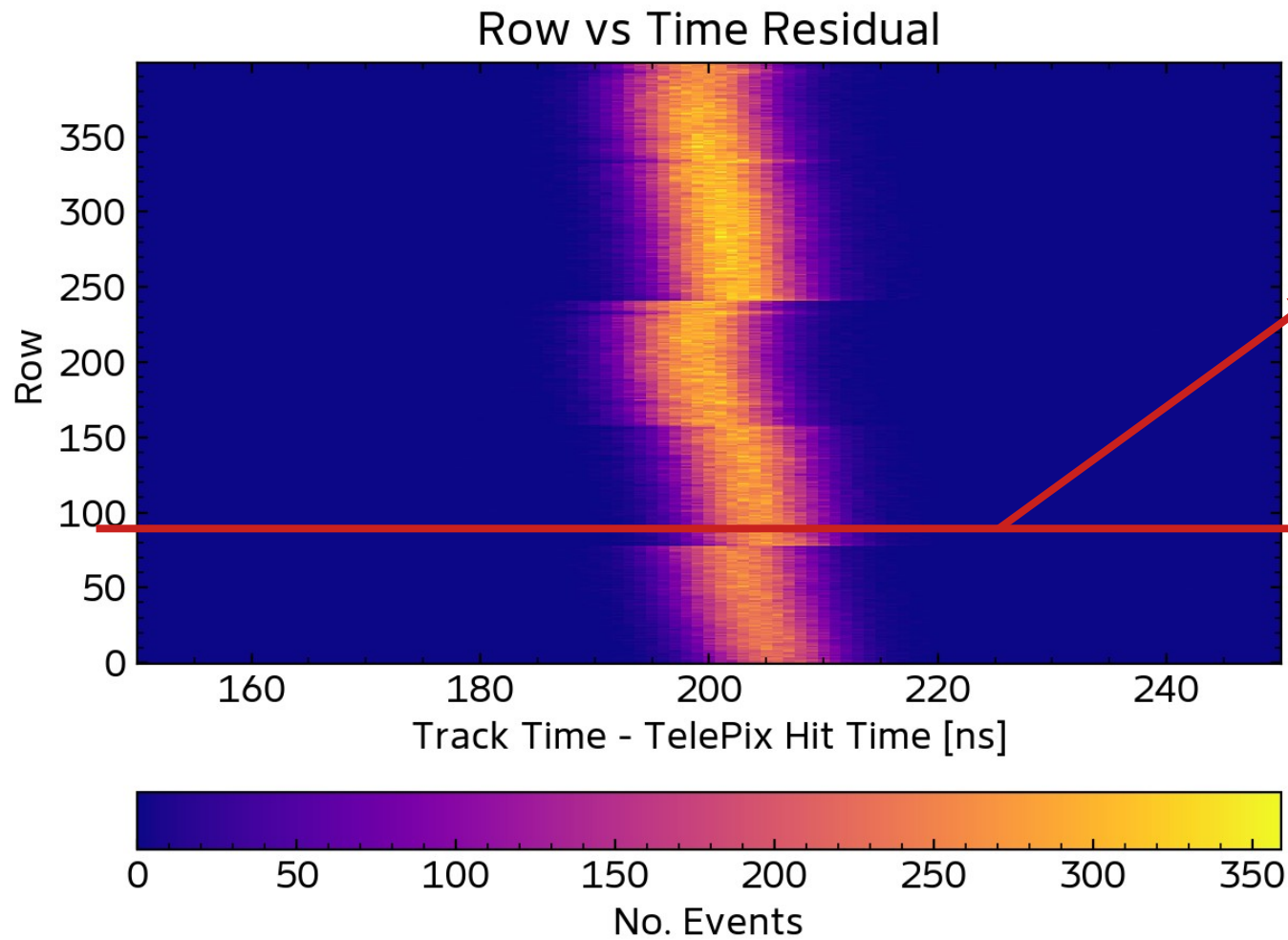
Bias 85 V and threshold 57 mV

Time Residual Corrections



Bias 85 V and threshold 57 mV

Time Residual Corrections



Gauss Fit

Extract Mean

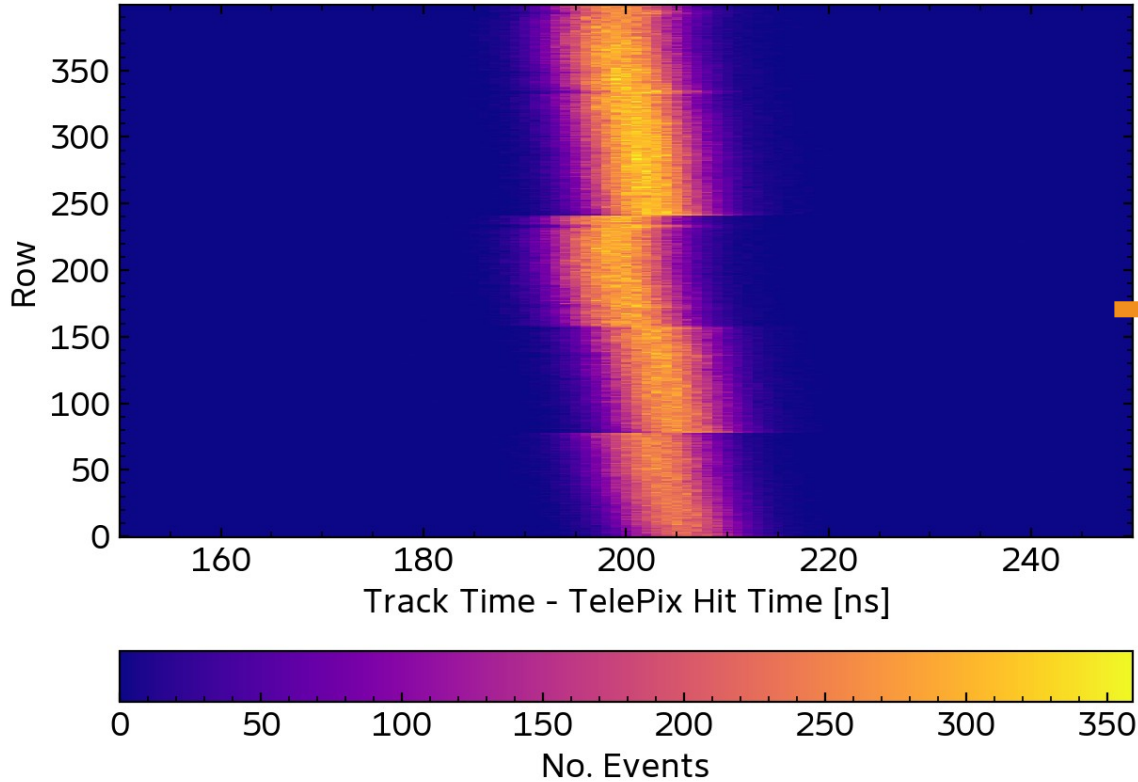
Reload data & Shift each timestamp by the mean

Bias 85 V and threshold 57 mV

Time Residual Corrections

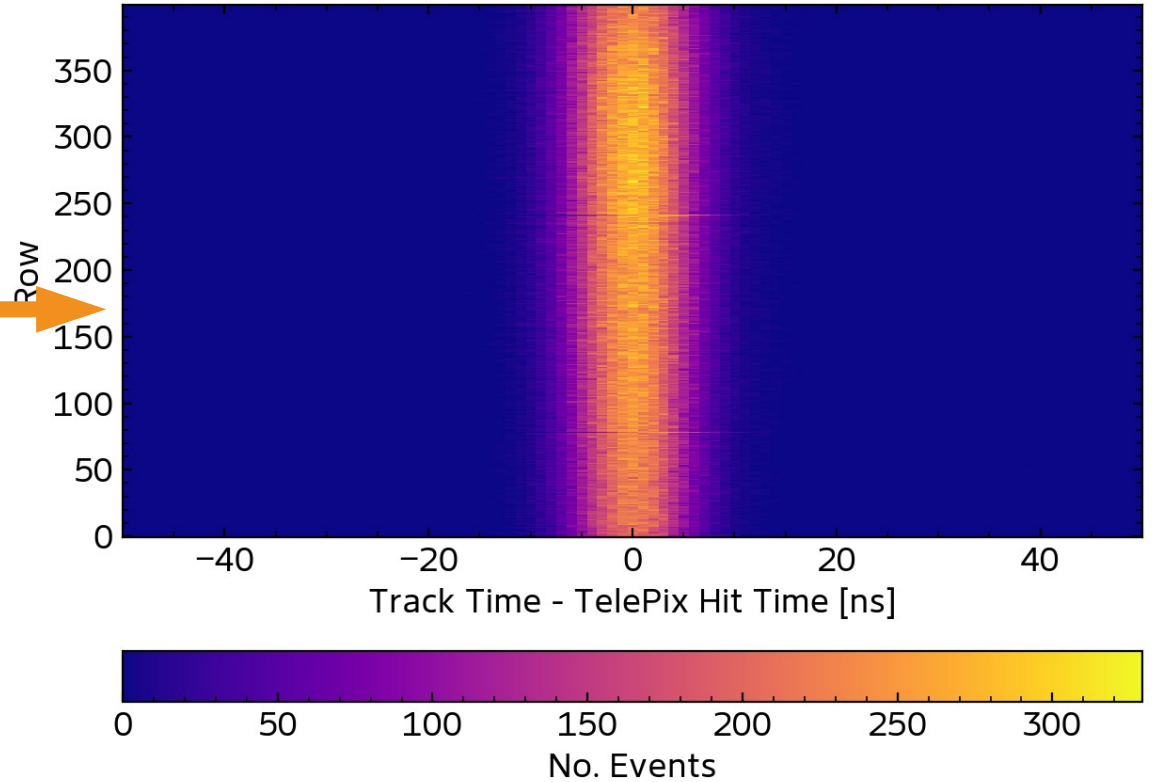
Before Corrections

Row vs Time Residual



After Corrections

Row vs Time Residual

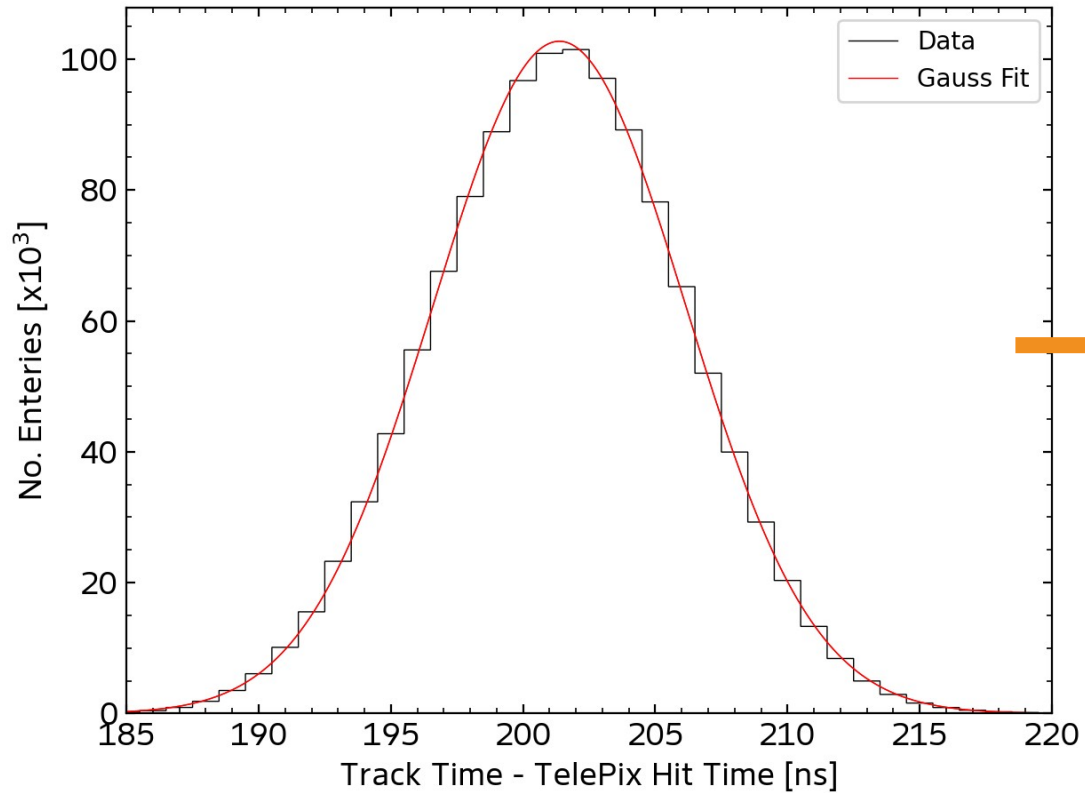


This must be done offline
And requires processing the data twice

Bias 85 V and
threshold 57 mV

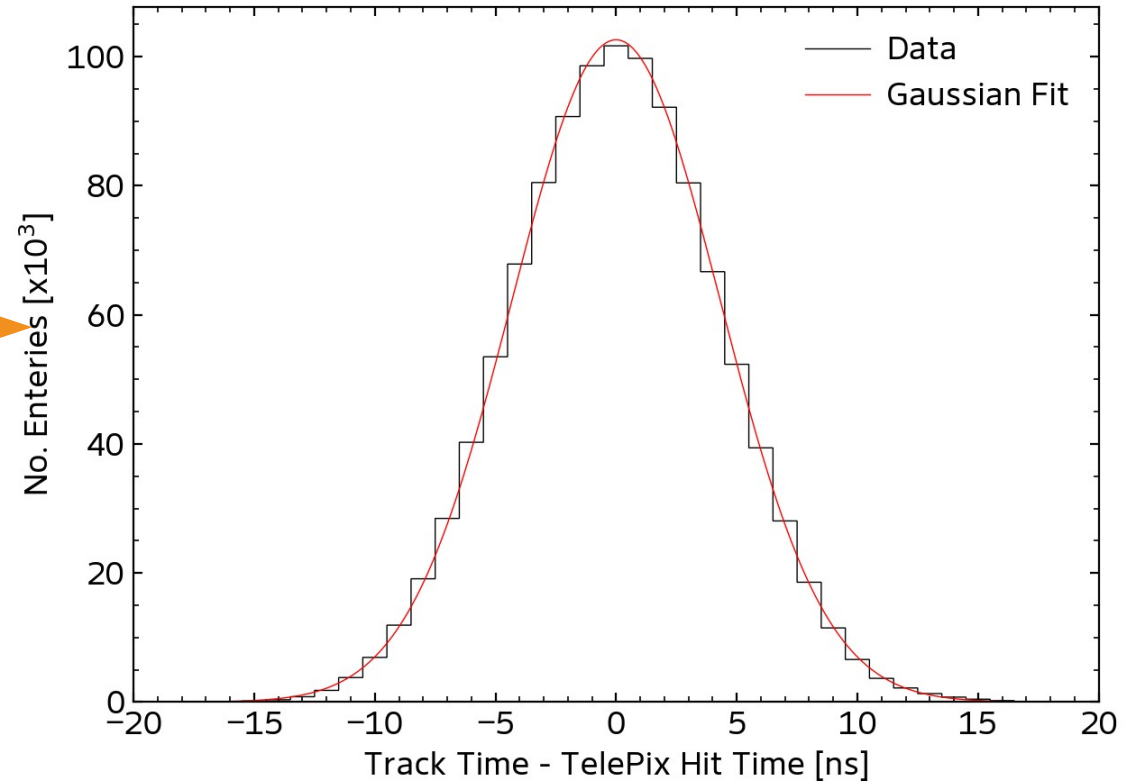
Time Residual Corrections

Before Corrections



4.781 ± 0.003 ns

After Corrections



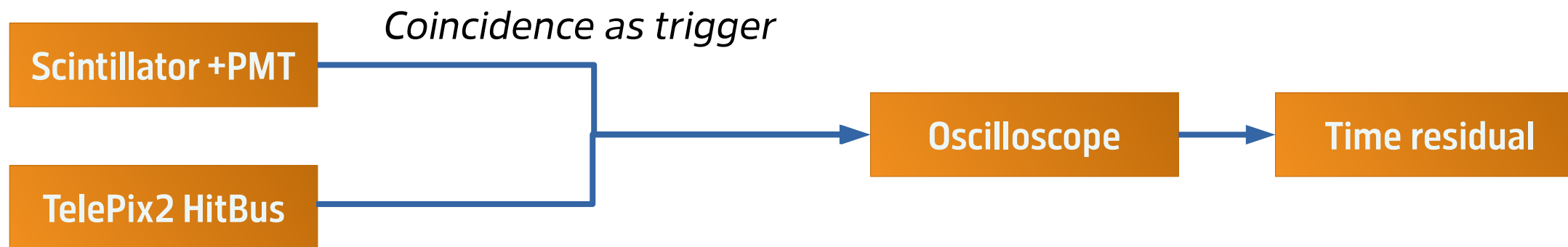
4.315 ± 0.003 ns

Bias 85 V and threshold 57 mV

HitBus Measurements

HitBus = Fast trigger output

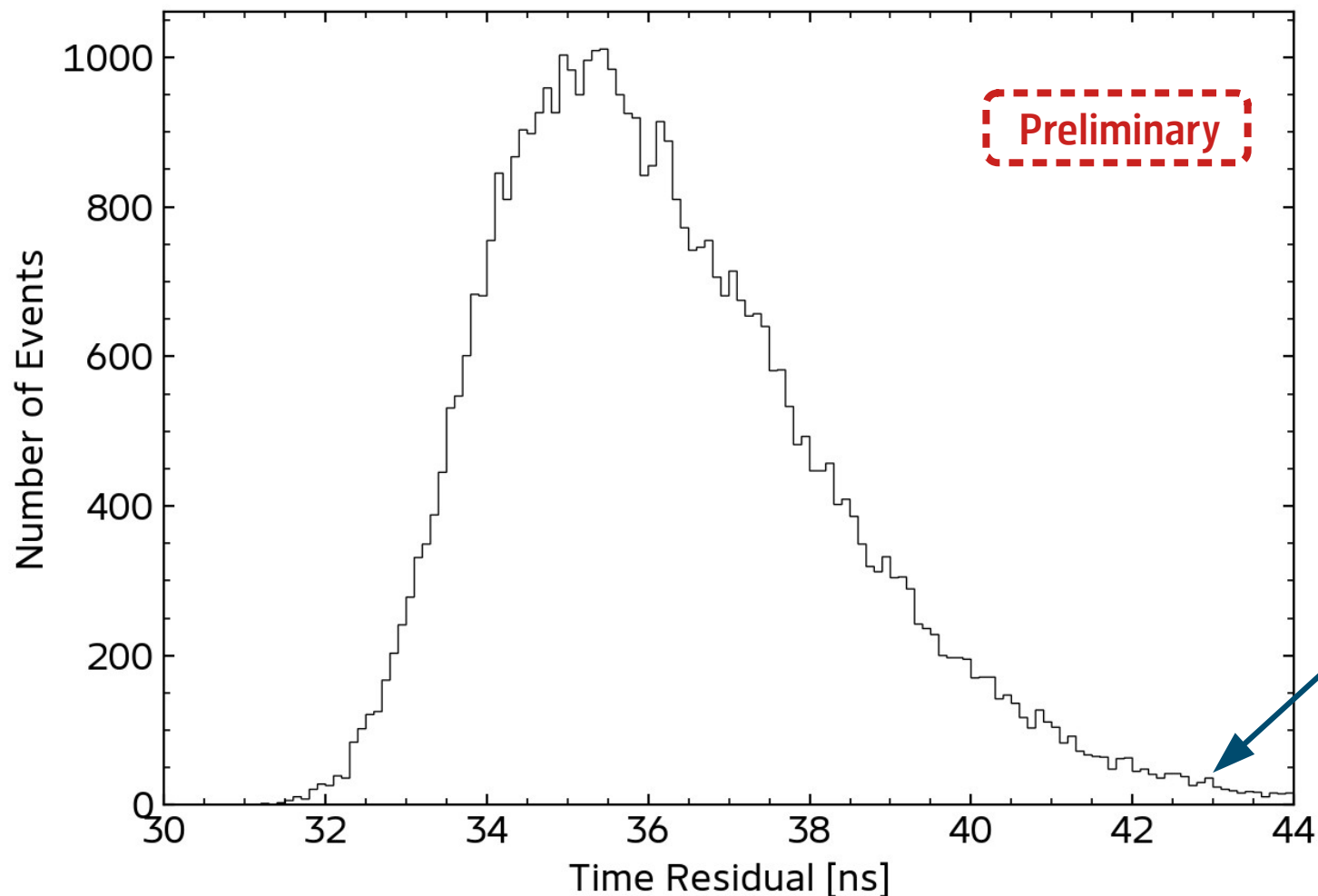
Method



Time Residual = Time at half maximum of scintillator – Time at half maximum of TelePix Hitbus

Hitbus Measurements

Result



Deviations from the standard Gauss distribution yet to be understood.

Preliminary measurements show an RMS of ≈ 2 ns

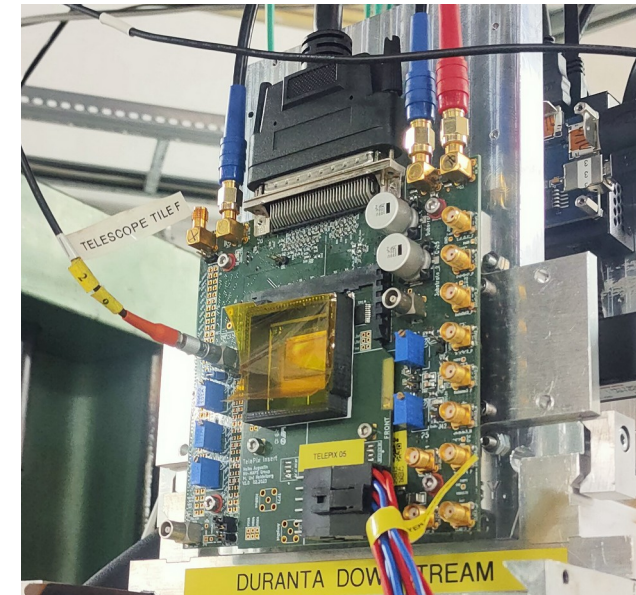
Taken with at a bias of 85 V and threshold of 64 mV

Slight background from imperfect triggering scheme

Conclusion

- Working ROI trigger
- Hitbus time resolution of $\approx 2 \text{ ns}$
- Efficiency $99.204 \pm 0.008 \%$
- Uncorrected time resolution $4.781 \pm 0.003 \text{ ns}$
- Offline corrected time resolution $4.315 \pm 0.003 \text{ ns}$

TelePix2 currently
being used by
users!



The measurements leading to these results have been performed at the Test Beam Facility at DESY Hamburg (Germany), a member of the Helmholtz Association (HGF)

Thank you for listening!

Questions?

Beam Telescopes at DESY II Testbeam facility

Most requested infrastructure by users (82% in 2022)

2 different types installed at desy **EUDET-Type** (TB21 & TB24) and **Adenium** (TB22)

	EUDET-Type	Adenium
Sensor	Mimosa26	Alpide
Active Area	2 x 1 cm	3 x 1.5 cm
Pixel Pitch	18.4 x 18.4 μm	29.24 x 26.88 μm
Read Out Time	> 115 μs	10 μs

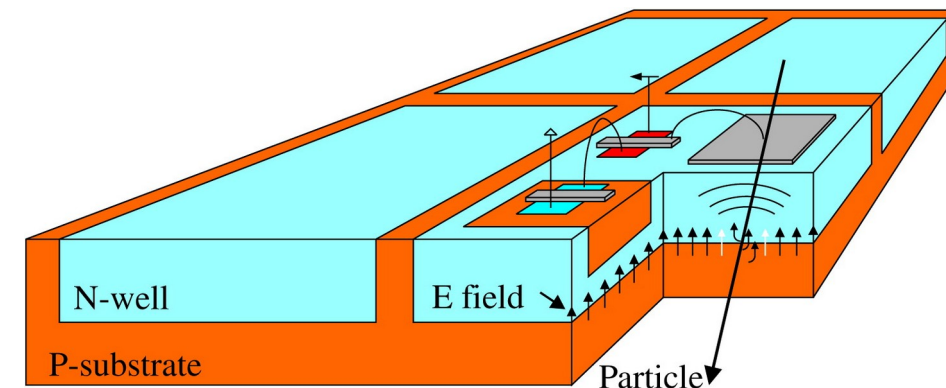
High-Voltage Monolithic Active Pixel Sensors

HV-MAPS

- **Hybrid** sensors bump bond a separate readout and sensor chip together
 - Can be **costly** to manufacture and have a **high material budget**
- **Monolithic** sensors integrate readout and sensor onto one chip:
 - But charge collection **via diffusion** → **too slow** for high rate applications

HV-MAPS embed readout inside pixel electrode

- **Higher biasing voltage** → collection **via drift (faster)**
- Can result in improved:
 - Signal amplitude
 - Charge collection speed
 - Radiation tolerance



Ivan Perić, NIM 582 (2007) 876-885